3.2 A Dual Input, Switch Mode Charger with Power Path

Description

The FAN5451x family of chargers includes an I^2C controlled 3.2 A USB-compliant switch-mode charger.

To facilitate fast system startup, the IC includes an optimized Power Path circuit which also accurately measures battery currents during charging and provides low impedance during discharge.

The charging parameters and operating modes are programmable through an I²C Interface. Charge status is reported back to the host through the I²C port and the / STAT pin.

The FAN5451x provides battery charging in three modes: Pre-Charge (IPP), Constant Current (CC) and Constant Voltage (CV). The charger can automatically restart the charge cycle when the battery falls below a restart voltage threshold. If the input source is removed, the IC enters a high-impedance mode, blocking battery current from leaking to either input.

The FAN5451x is available in a 63-bump, 0.4 mm pitch WLCSP package.

Features

- Fully Integrated, High–Efficiency Charger for Single–Cell Li–Ion and Li–Polymer Battery Packs
- Power Path Circuit ensures Fast System Startup with a Dead Battery
- 95% Charge Efficiency
- Charge Current Programmable up to 3.2 A
- 10 mV Float Voltage Accuracy
- ±5% Charge Current Regulation Accuracy
- 5 V, 1.5 A Boost Mode for USB OTG
- 22 V DC Withstand Voltage on VBUS
- 13.25 V Maximum Input Operating Voltage
- -2 V Input Reverse Polarity Protection

Benefits

- Secondary Input for Wireless Charging
- Dynamic Input Voltage Control (DIVC) for Operation with Weak Adapters
- USB BC1.2 Compatible
- Programmable 10 mA LDO
- Programmable Safety Timer with Reset Control
- Pin Configurable Ship Mode prevents Battery Discharge to System Load

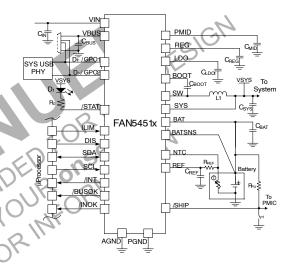
Applications

- Smart Phones
- Tablets



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ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

- Pin or Software Configurable Hardware Reset for Quick System Restart
- Battery Temperature Sensing Ensures Safe-To-Charge Operation (JEITA)
- Thermal Shutdown and Programmable Thermal Regulation
- High–Speed I²C Interface (3.4 Mb/s) with Fast Mode Plus Compatibility
- e-Books
- Li Ion Powered Devices

Table 1. ORDERING INFORMATION

Part Number	Package	Packing Method
FAN54510AUCX	63 - Bump, Wafer-Level Chip_Scale Package (WLCSP)	Tape and Reel
FAN54511AUCX	0.4 mm Pitch	
FAN54511APUCX		
FAN54512AUCX		
FAN54513AUCX		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Table 2. DEVICE ORDERING INFORMATION

Part Number	Slave Address	PN Bits: IC_INFO[5:3]	BC1.2 Detection	BC1.2 SDP I _{BUS} Current Limit	BC1.2 CDP/DCP I _{BUS} Current Limit	ILIM Pin Control	I _{BUS} Current Limit (ILIM Pin = HIGH)	I _{BUS} Current Limit (ILIM Pin = LOW)
FAN54510A (Note 1)	1101011_	000	ON (D+, D–)	2 min. @500 mA	Safety Timer @1500 mA	OFF	NA	N/A
FAN54511A	1101011_	001	OFF (GPO1,GPO2)	N/A	N/A	ON	500 mA	1500 mA
FAN54511AP	1101010_	001	OFF (GPO1,GPO2)	N/A	N/A	ON	500 mA	1500 mA
FAN54512A (Note 1)	1101011_	010	ON (D+, D–)	45 min. @100 mA	Safety Timer @1500 mA	OFF	N/A	N/A
FAN54513A	1101011_	011	OFF (GPO1,GPO2)	N/A	N/A	ON	100 mA	1500 mA
1. Contact ON for	r these options.	REP REP	OFF (GPO1,GPO2)	NTACE	04			

STATE DIAGRAMS

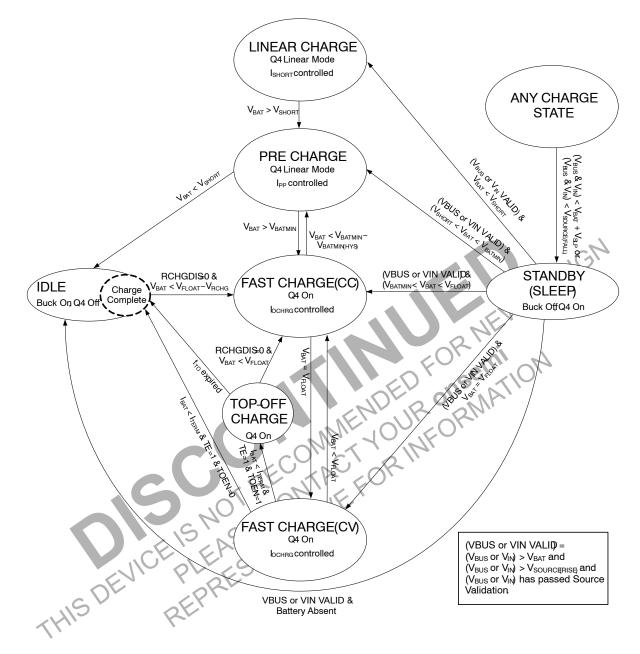


Figure 2. Charger State Diagram: State and Mode Transitions

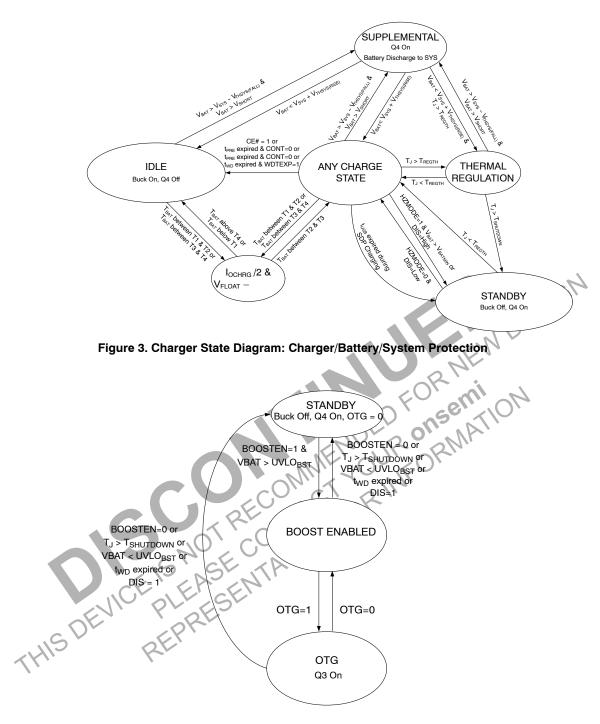
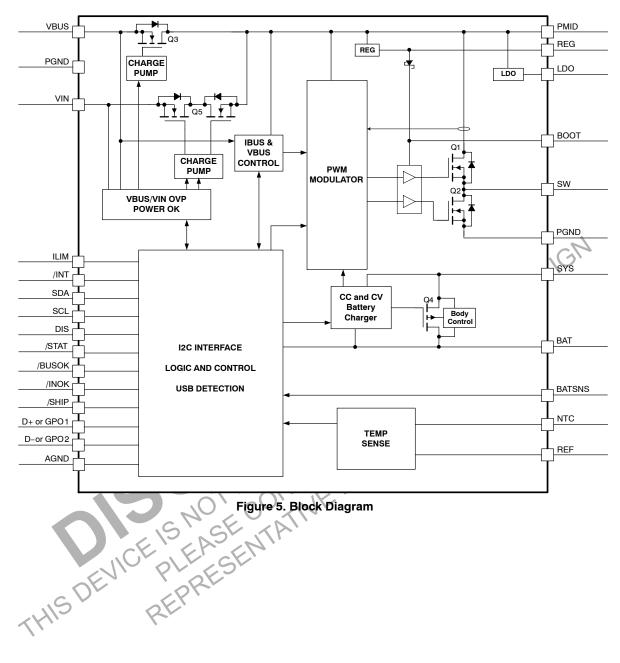


Figure 4. Boost State Diagram





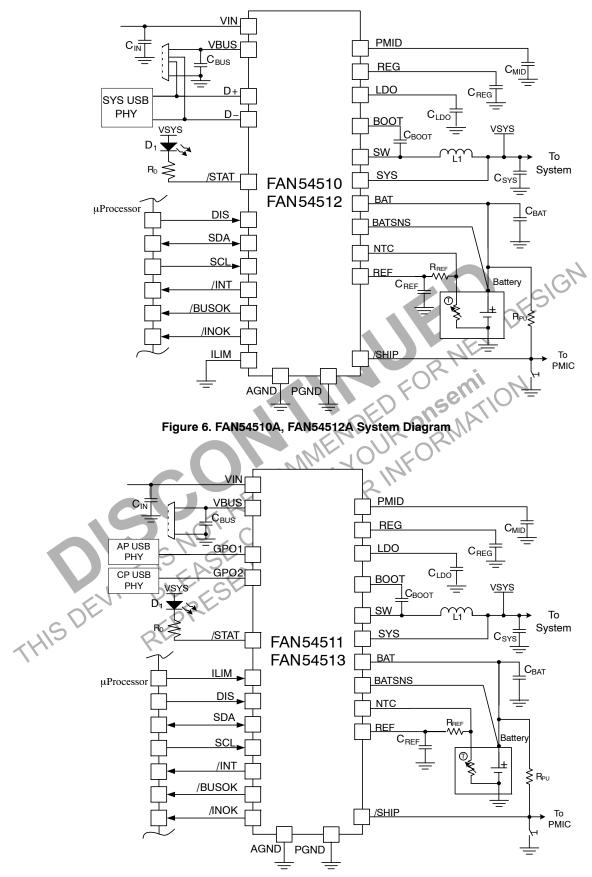


Figure 7. FAN54511A, FAN54511AP, FAN54513A System Diagram

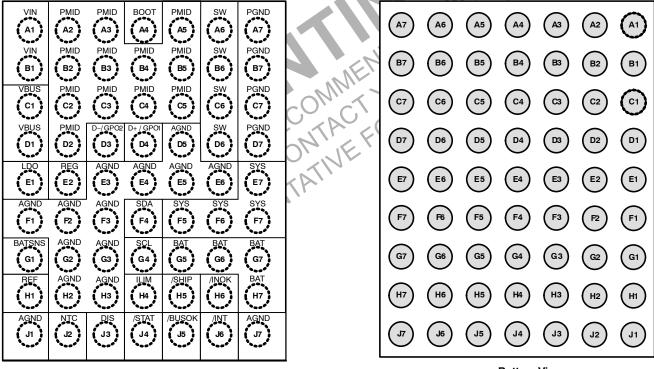
RECOMMENDED EXTERNAL COMPONENTS

Component	Description	Description Vendor		Тур.	Unit
L1	1.0 μH, +20/–10%, 4.1 A, 2520 x	SEMCO CIGT252010EH1R0MNE	L	1.0	μH
	1.0 mm	SEMCO CIGT2520TOERTROMINE	DCR	26	mΩ
C _{BAT} (Note 2)	22 $\mu\text{F},6.3$ V, 20%, X5R, 0603	TDK C1608X5R0J226M	С	22	Ē
C _{MID} x 2 (Note 3)	10 μF, 25 V, 10%, X5R, 0805	Murata GRM219R61E106M	С	10	μF
C _{BUS} , C _{IN}	1.0 μF, 25 V, 10% X5R, 0603	Murata GRM188R61E105K TDK: C1608X5R1E105M	С	1.0	nF
C _{SYS} (Note 4)	10 μF, 6.3 V, 20%, X5R, 0603	Murata GRM188R60J106M	С	10	
C _{REF,} C _{REG} , C _{LDO}	1.0 μF, 10 V, 20%, X5R, 0402	Murata GRM155R61A105M	С	1.0	μF
C _{BOOT}	10 nF, 10 V, 10%, X7R, 0201	Murata GRM033R71A103K	С	10	
R _{REF}	10 kΩ		R	10	kΩ
R _{PU}	1 MΩ		RC	Pi-	MΩ

2. A minimum effective capacitance of 3.6 μF is required after accounting for tolerance, temperature, and aging.

3. A minimum effective capacitance of 8 µF is required after accounting for tolerance, temperature, and aging.

4. Including CSYS, a minimum effective system capacitance (distributed) of 20 µF after accounting for tolerance, temperature, and aging is required.



Top View

Bottom View

Figure 8. WLCSP-63 Pin Assignments

Table 4. PIN DEFINITIONS

Pin #	Pin # Name Type Description					
POWER GROUND (LO	POWER GROUND (LOCAL PGND) REFERENCED PINS					
A1, B1	VIN	Р	Wireless Charger Input Voltage. From wireless receiver or second input power source. Bypass VIN to PGND with 1 $\mu\text{F}.$			
C1, D1	VBUS	Р	Charger Input Voltage. USB adapter input source also used for the USB–OTG output voltage. Bypass VBUS to PGND with 1 μF .			
A2, A3, A5, B2-B5, C2-C5, D2	PMID	PFP	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense. Bypass PMID to PGND locally with a minimum of $2x C_{MID}$.			
A6, B6, C6, D6	SW	Р	Switching Node. Connect to inductor L1 and CBOOT.			
A4	BOOT	Р	Bootstrap. High side NMOS Driver Bias. Connect a 10 nF capacitor between BOOT and SW.			
E7, F5–F7	SYS	Р	System Supply. Connect system load here. Bypass SYS to PGND locally with C_{SYS} .			
G5–G7, H7	BAT	Р	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass BAT to PGND with C_{BAT} .			
E1	LDO	AO	Linear Regulator. LDO is for powering external circuitry. Default output is 4.95 V when VBUS or VIN is valid.			
A7, B7, C7, D7	PGND	PG	Power Ground. Power return for gate drive and power transistors. The connection from these pins to the ground pads of C_{MID} and C_{SYS} should be as short as possible. Refer to Recommended Component Placement.			
ANALOG GROUND (A	AGND) REFE	RENCED I	PINS			

ANALOG GROUND (AGND) REFERENCED PINS

E2	REG	AFP	Internal Regulator. Bypass with a 1 µF capacitor to AGND
G1	BATSNS	AI	Battery Voltage Sense. Connect this pin as close to battery terminal as possible using a single trace. Do not use as a power pin.
H1	REF	AO	Reference Voltage. REF is a 1.8 V regulated output used in conjunction with the NTC pin to determine the battery temperature. Connect to a 1 μF capacitor to AGND.
J2	NTC	AI	Negative Temperature Coefficient Resistor. Pin is connected to the NTC terminal of the battery pack with a 10 k Ω external pull-up resistor to the REF pin. Note: Other values of the pull/up resistor and NTC may be used. See applications section for more detail.
D5, E3–E6, F1–F3, G2, G3, H2, H3, J1, J7	AGND	AGND	Analog Ground, All IC signals are referenced to this node. Connect to PGND at a single point. Refer to Recommended Component Placement.

SYSTEM GROUND (PGND) REFERENCED PINS

D4	D+	AI/O	Positive USB data line (FAN54510A, FAN54512A only). Used for BC1.2 adapter detec- tion of SDP, DCP, or CDP device connection.
	GPO1	DO	General Purpose Output 1 (FAN54511A, FAN54511AP, FAN54513A only). CMOS output driver that is sourced from the LDO output.
D3	D-	AI/O	Negative USB data line (FAN54510A, FAN54512A only). Used for BC1.2 detection of SDP or DCP/CDP device connection.
03	GPO2	DO	General Purpose Output 2 (FAN54511A, FAN54511AP, FAN54513A only). CMOS output driver that is sourced from the LDO output
F4	SDA	DI/O	I ² C Interface Serial Data. Open-drain, Bi-directional I ² C serial data line. This pin should not be left floating.
G4	SCL	DI	$\rm I^2C$ Interface Serial Clock. $\rm I^2C$ communication clock input. This pin should not be left floating.
H4	ILIM	DI	Input Current Limit for VBUS (FAN54511A, FAN54511AP, FAN54513A only). Input LOW sets the input current limit to 1.5 A and HIGH sets to 500 mA (FAN54511A, FAN54511AP only) or 100 mA (FAN54513A only). This pin is internally pulled down through a 1 M Ω resistor.
			ILIM pin functionality is disabled for FAN54510A and FAN54512A versions where it is recommended to tie ILIM to AGND or PGND.

H5	/SHIP	DI	Ship Mode Enable (Active–Low). If this pin is held LOW for more than $t_{SHIPENTER}$ during any other state, Ship Mode is entered and the battery is fully isolated from the system load. If /SHIP is held LOW again for more than $t_{SHIPEXIT}$, Ship mode is disabled and Q4 is configured to allow the battery to discharge to the system load. Ship mode can also be exited, automatically, by applying a valid input source. Tie this pin to BAT using a 1 M Ω pull–up resistor for devices with embedded batteries.
H6	/INOK	DO	VIN Power Okay (Active–Low). Active low, open–drain output indicates that the input source voltage at VIN has risen above V _{SOURCE(RISE)} and passed validation, and a valid VBUS is not present. /INOK remains low while V _{IN (FALL)} < V _{IN} < V _{INOVP} and V _{IN} > V _{BAT} . /INOK will be HIGH if /BUSOK is LOW.
J4	/STAT	DO	Status (Active–Low). Open–drain output indicating charge status. The IC pulls this pin LOW when charging is in progress, and can be used to signal the host processor or drive an LED.
J5	/BUSOK	DO	VBUS Power Okay (Active-Low). Active low, open-drain output indicates that the input source voltage at VBUS has risen above V _{SOURCE(RISE)} and passed validation. /BUSOK remains low while V _{BUS (FALL)} < V _{BUS} < V _{BUSOVP} and V _{BUS} > V _{BAT} .
J6	/INT	DO	Interrupt (Active–Low). Active low, open–drain output indicates that an interrupt bit or bits have been set. This pin is reset to HIGH after all set interrupt register bit(s) are read. This pin is not pulled LOW when an interrupt occurs that is masked by the associated mask bit.
J3	DIS	DI	Disable. If this pin is held HIGH, the PWM converter is disabled, creating a high impedance path between VBUS/VIN and SYS. This pin has an internal 1 M Ω pull-down.
THISD	EVICE	IS N PLE EPP	CONNENDED FOR NE OT RECONTACT OR INFORMATION SECUTATIVE FOR INFORMATION SECUTATIVE FOR INFORMATION

ABSOLUTE MAXIMUM RATINGS

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Table 5. ABSOLUTE	MAXIMUM RATINGS
-------------------	-----------------

Symbol	Parameter		Min	Max	Unit
	VBUS, PMID Voltage, Maximum Slew Rate of 2 V/ μ s (Note 6)		-2.0	22.0	
	VIN Voltage, Maximum Slew Rate of 2 V/ μ s (Not	e 6)	-2.0	16.0	
	BOOT Voltage		-0.3	19.0	
V _{DC}		DC	-0.3	14.0	
	SW Voltage	Transient: < 5 ns	-1.0	17.0	V
	SYS, BAT Voltage		-0.3	6.5 (Note 7)	
V _{DCO}	Voltage on Other Pins			6.5 (Note 7)	
	Electrostatic Discharge Protection Level, HBM	VBUS, PMID, VIN, BOOT, SW	12	50	
ESD	per JESD22-A114	All Other Pins	20	00	V
	Electrostatic Discharge Protection Level, CDM per JESD22–C101	All Pins	15	00	
TJ	Junction Temperature	OFP MS	-40	+150	°C
T _{STG}	Storage Temperature	CN R 2	-65	+150	°C
TL	Lead Soldering Temperature, 10 Seconds	NNE 100 COT		+260	°C

6. Positive slew rate applies only to voltages above the VIN_OVP or VBUS_OVP threshold.

7. Lesser of 6.5 V or V_{BAT} + 0.3 V.

RECOMMENDED OPERATING CONDITIONS

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. On Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Table 6. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Max.	Unit	
V _{BUS} , V _{IN}	Supply Voltage	4.50	13.25	V	
T _A	Ambient Temperature	-30	+85	°C	
TJ	Junction Temperature	-30	+100	°C	
C _{BAT}	Minimum Effective Capacitance on VBAT	3.6		μF	
C _{MID}	Minimum Effective Capacitance on PMID V _{BST} = 5 V		8		μF
C _{SYS_DISTRIBUTED}	Minimum Effective Capacitance on SYS (includes $\ensuremath{C_{SYS}}$ and distributed system capacitance)		20		μF
C _{LDO}	Minimum Effective Capacitance on LDO		0.4		μF
C _{REG}	Minimum Effective Capacitance on REG		0.4		μF

THERMAL PROPERTIES

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards without vias in accordance to

JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperature T_A .

Table 7. THERMAL PROPERTIES

Symbol	Parameter		Unit
θ_{JA}	Junction-to-Ambient Thermal Resistance	40	°C/W
Ψ_{JB}	Junction-to-Board Thermal Characterization Parameter (Evaluation Board)	4.3	°C/W

Table 8. ELECTRICAL SPECIFICATIONS

Unless otherwise specified: V_{BUS} = 5.0 V; V_{BAT} = 3.7 V; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; I_{REG} = I_{LDO} = 0 A; SCL, SDA = 0 or 1.8 V; and typical values are for T_A = 25°C

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
POWER SUPPLI	ES				10,	
		V _{BUS} > V _{SOURCE(RISE)} ; V _{IN} Open; PWM Switching; I _{BAT} = I _{SYS} = 0 A		AL.		mA
I _{SOURCE}	V _{BUS} or V _{IN} Current	V _{IN} > V _{SOURCE(RISE)} ; V _{BUS} Open; PWM Switching; I _{BAT} = I _{SYS} = 0 A	JEV	4		mA
		HZMODE= "1"; V _{SOURCE} > V _{SOURCE(RISE)} , NTC = GND	in	200	400	μA
		Sleep State; $V_{BUS} = V_{IN} = Open \text{ or } 0V;$ $V_{BAT} = 4.2 \text{ V}$	e T	O_3	10	μΑ
	Battery Discharge Current	Ship Mode State; $V_{BUS} = V_{IN} = Open$ or 0 V; $V_{BAT} = 4.2$ V	Nu	0.8	10	μΑ
I _{BAT_HZ}		DIS = HIGH or HZMODE="1"; V _{BUS} =5 V; V _{IN} = Open; V _{BAT} = 4.2V ; I _{SYS} = 0 A		1	10	μA
	S NOT R	DIS = HIGH or HZMODE ="1"; V _{BUS} = Open; V _{IN} = 5V; V _{BAT} = 4.2V; I _{SYS} = 0 A		1	10	μA
	Battery Leakage Current to V _{BUS} in High-Impedance Mode	V_{BUS} = 0 V; V_{IN} = Open; V_{BAT} = 4.2 V; I_{SYS} = 0 A		0.2	5.0	μΑ
ISOURCE_HZ	Battery Leakage Current to V _{IN} in High-Impedance Mode	V _{IN} = 0 V; V _{BUS} = Open; V _{BAT} = 4.2 V; I _{SYS} = 0 A		0.2	5.0	μA

CHARGER VOLTAGE REGULATION

THIS	Charge Voltage Range		3.30	 4.72	V
		$T_J = 25^{\circ}C; V_{FLOAT} = 4.20 V \text{ to } 4.50 V$	-6	+6	
V _{FLOAT}	Charge Voltage Accuracy	T_{J} = 0 to 70°C; V_{FLOAT} = 4.20 V to 4.50 V	-10	+10	mV
		T_J = -25 to 85°C; V_{FLOAT} = All Settings	-25	+25	

FAST CHARGE CURRENT REGULATION

	Output Charge Current Range	V _{BATMIN} < V _{BAT} < V _{FLOAT}	200	3200	mA
IOCHRG	Charge Current Accuracy	$I_{OCHRG} \ge 500 \text{ mA}, -30^{\circ}\text{C} < T_A < 85^{\circ}\text{C}$	-5	+5	%
		I _{OCHRG} < 500 mA, –30°C <t<sub>A< 85°C</t<sub>	-10	+10	70

PRE-CHARGE CURRENT CONTROL

I _{pp}	Pre-Charge Current Range		200		800	mA
	Pre-Charge Current Accuracy		-15		+15	%
I _{SHORT}	Linear Charging Current	V _{BAT} < V _{SHORT}	45	55	65	mA

Table 8. ELECTRICAL SPECIFICATIONS (continued)

Unless otherwise specified: $V_{BUS} = 5.0 \text{ V}$; $V_{BAT} = 3.7 \text{ V}$; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; $I_{REG} = I_{LDO} = 0 \text{ A}$; SCL, SDA = 0 or 1.8 V; and typical values are for $T_A = 25^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
CHARGE TERM	INATION DETECTION	-				
	Termination Current Threshold Range	V _{BAT} > V _{FLOAT} - V _{RCHG} ; V _{BUS} > V _{BAT}	25		600	mA
I _{TERM}	Termination Current Threshold	ITERM Setting > 200 mA	-10		+10	
	Accuracy	ITERM Setting = 100 mA to 200 mA	-20		+20	%
	Termination Current Deglitch Time			30		ms
WEAK BATTER	Y DETECTION	•				
	Weak Battery Threshold Range		3.0		3.7	V
	Hysteresis	FAN54512A Only		100	,GM	mV
V _{LOWV}		All Other Part Numbers		3)	ΠV
	Termination Current Threshold Accuracy		-5		+5	%
	Weak Battery Deglitch Time	Rising Voltage; 2 mV Overdrive		30		ms
MINIMUM BATT	ERY VOLTAGE DETECTION	FU	en.	07		-
V _{BATMIN}	Pre-charge to Fast Charge Transition Threshold Range	NDED one	2,7		3.4	V
	Hysteresis	ME OU FOR	180	265	350	mV
BATMIN	Threshold Accuracy	CONCIENN	-5		+5	%
	Deglitch Time	FOLLEDI		30		ms
BATTERY RECH	IARGE THRESHOLD	ONTE				
V _{RCHG}	Recharge Threshold	Below V _{FLOAT} ; T _J = 25°C		170		m۷
· NORG	Deglitch Time	V_{BAT} falling below V_{RCHG} threshold		130		ms
SHORTED BAT	TERY THRESHOLD					
V _{SHORT}	Battery Short-Circuit Threshold	V _{BAT} Rising	1.94	2.00	2.06	V
BATTERY FET	SUPPLEMENTAL CONTROL					
	BAT to SYS Threshold for BATFET	$V_{SYS -} V_{BAT,}$ Falling V_{SYS}	-6	-5	-4	
V _{THSYS}	Gate transition while charging	$V_{SYS -} V_{BAT,}$ Rising V_{SYS}	0	1	2	mV
BATTERY TEMP	PERATURE DETECTION	•				
T1	T1 (0°C) Temperature Threshold		71.9	73.9	75.9	
T2	T2 (10°C) Temperature Threshold		62.6	64.6	66.6	% 0
Т3	T3 (45°C) Temperature Threshold		30.9	32.9	34.9	VRE
T4	T4 (60°C) Temperature Threshold		21.3	23.3	25.3	
V _{JEITA} (Note 9)	FLOAT Voltage Reduction During JEITA Region	V _{FLOAT} = 4.35 V	160	200	240	m۷

Table 8. ELECTRICAL SPECIFICATIONS (continued)

Unless otherwise specified: V_{BUS} = 5.0 V; V_{BAT} = 3.7 V; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; I_{REG} = I_{LDO} = 0 A; SCL, SDA = 0 or 1.8 V; and typical values are for T_A = 25 $^\circ C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
INPUT POWER S	OURCE DETECTION					
V _{SOURCE(RISE)}	$\rm V_{BUS}$ or $\rm V_{IN}$ Input Voltage Rising	To Initiate Source Validation	4.30	4.40	4.52	V
V _{SOURCE(FALL)}	Minimum V_{BUS} or V_{IN}	During Charging, V _{BAT} < 3.6 V	3.55	3.70	3.80	V
V _{SLP}	Sleep–Mode Entry Threshold, V _{SOURCE} – V _{BAT}	VSOURCE(FALL) ≤[¥BAT	0	40	100	mV
^t SRCQUAL	V_{BUS} or V_{IN} Input Qualification Time			32		ms
tvsc_valid	V_{BUS} or V_{IN} Input Validation Time			32		ms
IVSOURCE	V_{BUS} or V_{IN} Input Validation Current			50		mA
DIVC CONTROL	LOOP				JCP	
V _{SOURCE} (LIM)	Input Voltage Loop Setpoint Accuracy		-3	DE	+3	%

INPUT CURREN	T LIMIT		EV	1		
	V _{BUS} Input Current Limit Range	R	100		3000	
		ILIM = HIGH (100 mA) FAN54513A Only	86	93	100	
		ILIM = HIGH (500 mA) FAN54511A, FAN54511AP Only	460	480	500	
I _{BUSLIM}	V _{BUS} Input Current Limit Threshold	ILIM = LOW (1.5 A); FAN54511A, FAN54511AP, FAN54513A Only	1380	1440	1500	mA
		1BUSLIM (REG 14h[6:0]) = "00h"	86	93	100	
		IBUSLIM (REG 14h[6:0]) = "10h"	460	480	500	
	SNGE	IBUSLIM (REG 14h[6:0]) = "74h"	2760	2880	3000	
	V _{IN} Input Current Limit Range		325		2000	
I _{INLIM}	A harvet Current Limit Throughold	INLIM (REG 16h[6:0]) = "1Bh"	920	960	1000	mA
,19	VIN Input Current Limit Threshold	INLIM (REG 16h[6:0]) = "43h"	1840	1920	2000	

LOW DROP OUT REGULATOR

V _{LDOACC}	LDO Voltage Accuracy	V _{PMID} ≥[]¥ _{LDO} + 500 mV; I _{LDO} = 1 mA	-5		+5	%
I _{LDO}	Current Rating	$V_{PMID} = V_{LDO} + 500 \text{ mV}$	10			mA
VLDO _{DROP} (Note 10)	Drop Out Voltage	I _{OUT} = 10 mA		170		mV
RLDO _{PD}	LDO Pull Down Resistance when Disabled	LDO Off		1.2		kΩ
IQ _{LDO}	LDO Quiescent Current	LDO On, V _{PMID} = V _{LDO} + 500 mV		20	40	μA
REG _{LDO}	LDO Load Regulation	V _{PMID} = V _{LDO} + 500 mV; 10 μA < I _{OUT} ≤[]0 mA		50		mV

Table 8. ELECTRICAL SPECIFICATIONS (continued)

Battery Detection Time

t_{DETECT}

Unless otherwise specified: V_{BUS} = 5.0 V; V_{BAT} = 3.7 V; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; I_{REG} = I_{LDO} = 0 A; SCL, SDA = 0 or 1.8 V; and typical values are for T_A = 25°C

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
GPO1, GPO2 (F	AN54511A, FAN54511AP, FAN54513A	ÓNLY)	•			
V _(OL)	Output Low	I _{SINK} = 5 mA			0.3	V
V _(OH)	Output High	I _{SOURCE} = 5 mA	V _{LDO} – 200 mV			v
V _{REF} BIAS GEN	ERATOR					
	Bias Regulator Voltage	$V_{SOURCE} > V_{SOURCE(MIN)}$		1.8		V
V _{REF}	Short-Circuit Current Limit			2.5		μA
/STAT, /BUSOK,	/INOK, /INT, SDA					
V _(OL)	Output Low	I _{SINK} = 5 mA			0.4	V
I _(OH)	Output High Leakage Current	VDD = 5 V			2 1	μA
LOGIC LEVELS	: SDA, SCL, /SHIP, ILIM, DIS			10×		
V _{IH}	High-Level Input Voltage		1.05			V
V _{IL}	Low-Level Input Voltage		in the second se	1	0.4	V
I _{IN}	Input Bias Current	Input Tied to GND or V _{BUS}	e	0.01	1.00	μA
DIS, ILIM		DE ON	NA,	7		
R _{PD} (Note 11)	Pull Down Resistance	MELOUZOF		1		M۵
D+/D- DETECTI	ON (FAN54510A, FAN54512A ONLY)	ONIT TO INT				
V_{DP_SRC}	D+ Source Voltage	0 to 300 µA	0.5	0.6	0.7	V
V_{DM_SRC}	D- Source Voltage	0 to 300 μΑ	0.5	0.6	0.7	V
V _{DAT_REF}	Data Detect Voltage	ATT	0.25		0.40	V
I _{DP_SRC}	Data Contact Detect Current Source	211	7		13	μΑ
I _{DP_SNK}	D+ Sink Current		25		175	μA
IDM_SNK	D- Sink Current		25		175	μA
VLGC_HI	Logic High Threshold		2			V
V _{LGC_LO}	Logic Low Threshold				0.8	V
R _{DM_DWN}	D– Pulldown Resistor		14.25		24.80	kΩ
C _{OFF} (Note 9)	D+, D- Off Capacitance	D+, D- = Hi-Z; f = 1 MHz, V _{BIAS} = 0.2 V		4		pF
BATTERY ABSE						- <u> </u>
I _{DETECT} (Note 12)	Battery Detection Current before Charge Done (Sink Current)	Begins after Termination Detected and before		-8		m/
					1	1

 $V_{BAT} \leq V_{FLOAT} - V_{RCHG}$

262

ms

Table 8. ELECTRICAL SPECIFICATIONS (continued)

Unless otherwise specified: V_{BUS} = 5.0 V; V_{BAT} = 3.7 V; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; I_{REG} = I_{LDO} = 0 A; SCL, SDA = 0 or 1.8 V; and typical values are for T_A = 25 $^\circ C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
POWER SWITCI	HES	-				
		VBUS to PMID; I _{BUS} = 300 mA		360		
	Resistance of VBUS Blocking FET (Q3)	VBUS to PMID; I _{BUS} = 900 mA		82		
		VBUS to PMID; I _{BUS} = 3000 mA		28		
	Resistance of VIN Blocking FET (Q5)	VIN to PMID		135		
R _{DS(ON)}	Resistance of Buck High Side FET (Q1)	PMID to SW		24		mΩ
	Resistance of Buck Low Side FET (Q2)	SW to GND		19	GN	
	Bosistones of RATEET (04)	SYS to BAT; VBAT = 4.2 V; I _{OCHG} = 500 mA		55)	
	Resistance of BATFET (Q4)	SYS to BAT; VBAT = 4.2 V; I _{OCHG} = 1.5 A	NEV	15		
HARGER PWN	I MODULATOR	EON	in	2		

CHARGER PWM MODULATOR

f _{SW}	Oscillator Frequency		ED	Sel T	01.5		MHz	Ī
D _{UTY} (Note 9)	Duty Cycle		NPR	0		99.6	%	Ī

BOOST MODE OPERATION (BOOSTEN (REG 1Ch[5]) = OTG (REG 1Ch[6]) = "1")

	Programmable Boost Output Voltage Range	2.5 V VBAT < 45 V	4.940		5.347	
V _{BOOST}	Boost Output Voltage at VBUS	2.5 V < V _{BAT} < 4.5 V; V _{BST} = 5 V; I_{LOAD} from 0 to 900 mA	4.85	5.00	5.25	V
		3.0 V < V _{BAT} < 4.5 V; V _{BST} = 5 V; I _{LOAD} from 0 to 1500 mA	4.75	5.00	5.25	
I _{BAT(BOOST)}	Boost Mode Quiescent Current	V _{BAT} = 3.6 V; I _{LOAD} = 0 A		300	575	μA
I _{LIMPK(BST)} (Note 9)	Q2 Peak Current Limit		3.3	4.1	5.7	А
UVLO _{BST}	Minimum Battery Voltage for Boost	While Boost Active		2.32		V
	Operation	To Start Boost Regulator		2.48	2.70	v

PROTECTION AND TIMERS

	V _{BUS} Rising; VBUSOVP (REG 15h[5:4]) = "00"			6.50	6.65	
V _{BUSOVP}	VBUS Over-Voltage Threshold	V _{BUS} Rising; VBUSOVP (REG 15h[5:4] = "01"	10.25	10.50	10.75	V
		V _{BUS} Rising; VBUSOVP (REG 15h[5:4] = "10"	13.4	13.7	14.0	
V _{BUSOVP(HYS)}	V _{BUSOVP} Hysteresis	V _{BUS} Falling		100		mV

Table 8. ELECTRICAL SPECIFICATIONS (continued)

Unless otherwise specified: V_{BUS} = 5.0 V; V_{BAT} = 3.7 V; HZMODE = "0"; BOOSTEN = "0" (Charge Mode); TREGTH = 120°C; I_{REG} = I_{LDO} = 0 A; SCL, SDA = 0 or 1.8 V; and typical values are for $T_A = 25^{\circ}C$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
PROTECTION AN	ND TIMERS					
		V _{IN} Rising; VINOVP (REG 17h[5:4]) = "00"	6.35	6.50	6.65	
VINOVP	V _{IN} Over-Voltage Threshold	V _{IN} Rising; VINOVP (REG 17h[5:4]) = "01"	10.25	10.50	10.75	V
		V _{IN} Rising; VINOVP (REG 17h[5:4]) = "10"	13.4	13.7	14.0	
V _{BUSOVP(HYS)}	V _{INOVP} Hysteresis	V _{IN} Falling		100		m٧
V _{BOOST OVP}	Boost Over-Voltage Threshold	BOOSTEN (REG 1Ch[5] = "1"; V _{BUS} Rising	5.8	5.9	6.1	V
- BOOS1_OVF	Hysteresis	V _{BUS} Falling	\frown	100	,GN	m∖
	Battery Over-Voltage Threshold	Rising	1.025* V _{FLOAT}	1.050* Vfloat	1.075* V _{FLOAT}	V
VBAT_OVP	Hysteresis	V _{BAT} Falling relative to Rising Threshold	NEV	1		%
I _{LIMPK(CHG)} (Note 9)	High-Side Cycle-by-Cycle Peak Current Limit (Q1)	Charge Mode	4.6	4.9	5.4	A
I _{LIMQ4SC}	Q4 Short Circuit Current Limit	EV	6.6	9.0		Α
t SCQUAL	Q4 Short Circuit Qualification Time	NUR	Nr.	1		ms
tSCRECOV	Q4 Short Circuit Recovery Time	ME'OU'COF	÷.	2		se
t_{SHIPENTER}	Hardware Ship Mode Entry Time	Not in Ship Mode		8		se
t _{SHIPEXIT}	Hardware Ship Mode Exit Time	In Ship Mode		4		se
T _{SHUTDOWN} (Note 9)	Thermal Shutdown Threshold during Charging	T _J Rising		150		°C
(Note 3)	Hysteresis	T_{J} Falling		T _{REGTH}		
T _{REGTH} (Note 9)	Thermal Regulation Threshold dur- ing Charging or Thermal Shutdown Threshold during Boost Operation	REG 0Fh[6:5]) = "10"		100		°C
t _{INT}	Battery Detection Interval while the Battery is Removed			2.1		se
t _{FAST}	Safety Timer – Fast Range		240		960	mir
t _{PRE}	Safety Timer – Pre Range		1.667		36.000	mir
t _{TO}	Top Off Timer		10		70	mi
		FAN54510A SDP Attached		100	120	se
t _{USB}	USB Timer	FAN54512A SDP Attached		36	45	mi
t _{SAFE_ACC}	Safety Timer Accuracy		-20		20	%
		Charger Enabled	80	100	120	se
t _{WD}	Watch Dog Timer	Charger Disabled	73	100	127	%
Δt _{L F} (Note 13)	Low-Frequency Timer Accuracy	Charger Inactive	-27		27	%

8. Limits over the recommended temperature operating range (-30 to 85 °C) are correlated by statistical quality control methods.

2. Limits over the recommended temperature operating range (-30 to 85 °C) are correlated by statistical quality control methods.
 9. Guaranteed by design and/or Characterization; not tested in production.
 10. Dropout voltage is determined by reducing the LDO input voltage until the LDO output voltage falls to 98% of its regulated voltage. Under this condition, PMID – VLDO (MEASURED) = VLDODROP.
 11. In LOW state, the pull-down is present. In HIGH state, the pull-down is released.
 12. Negative current is current flowing from the battery to GND (discharging the battery).

13. This tolerance (%) applies to all timers on the IC, including soft-start and deglitch timers.

Table 9. I²C TIMING SPECIFICATIONS

Symbol	Parameter	Condition	Min.	Тур.	Max.	Uni	
		Standard Mode			100		
		Fast Mode			400		
f _{SCL}	SCL Clock Frequency	Fast Mode Plus			1000	kHz	
		High–Speed Mode, $C_B \leq 100 \text{ pF}$			3400		
		High–Speed Mode, $C_B \le 400 \text{ pF}$			1700		
		Standard Mode		4.7			
t _{BUF}	Bus-free Time between STOP and START Conditions	Fast Mode		1.3		μs	
		Fast Mode Plus		0.5			
		Standard Mode		4		με	
	START or Repeated START Hold	Fast Mode		600	~	ns	
t _{HD;STA}	Time	Fast Mode Plus		260	slQ,	ns	
		High-Speed Mode		160		ns	
	Standard Mode	JE	4.7		με		
		Fast Mode		1.3		με	
t _{LOW}	SCL LOW Period	Fast Mode Plus	en	0,5		με	
		High–Speed Mode, $C_B \leq 100 \text{ pF}$	An,	160		ns	
	High–Speed Mode, $C_B \leq 400 \text{ pF}$	2/4	320		ns		
		Standard Mode		4		με	
		Fast Mode		600		ns	
t _{HIGH}	SCL HIGH Period	Fast Mode Plus		260		ns	
	GNOF	High–Speed Mode, $C_B \leq 100 \text{ pF}$		60		ns	
	CE IS NO FASE	High–Speed Mode, $C_B \leq 400 \text{ pF}$		120		ns	
	EVIL PLESE	Standard Mode		4.7		με	
, C	Repeated START Setup Time	Fast Mode		600		ns	
t _{SU;STA}	Repeated START Setup Time	Fast Mode Plus		260		ns	
Ţ		High-Speed Mode		160		ns	
		Standard Mode		250			
t	Data Setup Time	Fast Mode		100		n	
^t su;dat	Data Setup Time	Fast Mode Plus		50		ns	
		High-Speed Mode		10			
		Standard Mode	0		3.45	μ	
		Fast Mode	0		900	ns	
t _{HD;DAT}	Data Hold Time	Fast Mode Plus	0		450	ns	
		High–Speed Mode, $C_B \le 100 \text{ pF}$	0		70	ns	
		High–Speed Mode, C _B ≤ 400 pF	0		150	ns	

Table 9. I ² C TIMING SPECIFICATIONS	(continued)
-------------------------------------------------	-------------

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit	
		Standard Mode	20+0	.1C _B	1000		
		Fast Mode	20+0.1C _B		300		
t _{RCL}	SCL Rise Time	Fast Mode Plus	20+0	.1C _B	120	ns	
		High–Speed Mode, $C_B \leq 100 \text{ pF}$		10	0 80		
		High–Speed Mode, $C_B \leq 400 \text{ pF}$		20	160		
		Standard Mode	20+0	.1C _B	300		
		Fast Mode	20+0	.1C _B	300		
t _{FCL}	SCL Fall Time	Fast Mode Plus	20+0	.1C _B	120	ns	
	High–Speed Mode, $C_B \leq 100 \text{ pF}$		10	40			
		High–Speed Mode, $C_B \leq 400 \text{ pF}$		20	80		
	Rise Time of SCL after a Repeated	High–Speed Mode, $C_B \leq 100 \text{ pF}$		10	80	ns	
t _{RCL1}	START Condition and after ACK Bit	High–Speed Mode, $C_B \le 400 \text{ pF}$		20	160		
		Standard Mode	20+0	.1C _B	1000		
		Fast Mode	20+0	.1C _B	300	ns	
t _{RDA}	SDA Rise Time	Fast Mode Plus	20+0	.1C _B	120		
		High–Speed Mode, $C_B \le 100 \text{ pF}$		10	80		
		High–Speed Mode, $C_B \le 400 \text{ pF}$	elu,	20	160		
		Standard Mode	20+0	.1C _B	300		
		Fast Mode	20+0	.1C _B	300		
t _{FDA}	SDA Fall Time	Fast Mode Plus	20+0.1C _B		120	ns	
		High–Speed Mode, C _B ≤ 100 pF		10	80		
		High–Speed Mode, C _B ≤ 400 pF		20	160		
	· CV / P	Standard Mode		4		μs	
		Fast Mode		600		ns	
t _{SU;STO}	Stop Condition Setup Time	Fast Mode Plus		120		ns	
	CE CAS	High-Speed Mode		160		ns	
CB	Capacitive Load for SDA and SCL	7			400	pF	

CIRCUIT OVERVIEW

The FAN5451x combines a highly integrated synchronous buck regulator for battery charging and providing system power. The converter can also operate as a boost regulator, which can supply 5 V to USB On–The–Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost operations to maintain high efficiency over a wide range of adapter input voltage and battery voltages.

With dual inputs, the charger can quickly switch between multiple power sources. For example, the charger can be powered from a wireless power receiver until plugged into a traditional USB or wall adapter.

An integrated Power Path FET facilitates fast system startup. This FET also accurately senses charging current, thus eliminating the need for an external sense resistor. Additionally, the FET provides a low impedance path from the battery to the system.

OPERATING MODES

The FAN5451x has seven operating modes:

Linear Mode:

When $V_{BAT} < V_{SHORT}$ (2.0 V), the buck converter regulates voltage at SYS and provides the system current enabling instant turn on of the system. The BATFET (Q4) charges the battery at the I_{SHORT} current to safely recover the battery.

Pre-Charge Mode:

Above V_{SHORT} , the buck converter regulates voltage at SYS and provides the system current. The BATFET (Q4) is operated as a linear current source to pre-charge the battery under I_{PP} control.

Fast Charge Mode:

The BATFET (Q4) is fully enhanced, charging the battery under I_{OCHRG} control either in the Constant Current Mode or Constant Voltage Mode from the output of the buck regulator.

System Mode (Idle State):

The buck converter regulates voltage at SYS and provides the system current, while the battery is not being charged. This mode can occur if the battery charging has terminated or charging is disabled.

Supplemental Mode

The buck converter cannot produce enough current to maintain V_{SYS} above V_{BAT} . The BATFET (Q4) is fully enhanced to provide supplemental current from the battery to the system load.

Boost Mode

Q1 and Q2 operate as a synchronous boost regulator to provide power to the VBUS pin for USB-On-the-Go (OTG) applications using the battery as its input. The boost converter output voltage is programmable.

High-Impedance Mode (Standby State)

Both the boost and charging circuits are OFF and the battery is providing current to the system. Current flow from VBUS or VIN to the battery or from the battery to VBUS or VIN is blocked.

CONFIGURABLE CHARGE PARAMETERS

The following charging parameters can be programmed by the host through I^2C :

Pre-Charge Current Regulation (IPP)

Limits the maximum battery charging current when $V_{SHORT} < V_{BAT} < V_{BATMIN}$. The default setting is 450 mA. See *PRECHG* (REG 13h[3:0])

Minimum Battery Threshold (VBATMIN)

Sets the battery voltage threshold for transitioning between Pre-Charge and Fast Charge. V_{BATMIN} should not be set lower than the minimum required system voltage. The default setting is 3.4 V.

See VBATMIN (REG 0Ch[2:0])

Regulated System Voltage (V_{SYS})

Regulates the system voltage when $V_{BAT} < V_{BATMIN}$. VSYS should be programmed 200 mV, or more, above the minimum required system voltage. The default setting is 3.6 V.

See VSYS (REG 0Dh[1:0])

Fast Charge Current Regulation (IOCHRG)

Limits the maximum battery charging current when $\ensuremath{V_{BAT}}$

> V_{BATMIN}. The default setting is 1000 mA. See *IOCHRG* (REG 12h[5:0])

Thermal Regulation (T_{REG})

Limits charge current to prevent the IC from overheating. The default setting is 100°C.

See TREGTH (REG 0Fh[6:5])

Output Voltage Regulation (V_{FLOAT})

Maximum battery charging voltage. The default setting is 4.35 V.

See FLOAT (REG 11h[7:0])

Charge Termination Threshold (I_{TERM})

Terminates charging at the desired current when TE (termination enable)="1". The default setting is 300 mA.

See *ITERM* (REG 13h[7:4])

CONFIGURABLE INPUT POWER PARAMETERS

The following input power parameters can be programmed by the host through I^2C :

VBUS Input Current Limit (IBUSLIM)

Limits the amount of current drawn from the VBUS source. The default setting is 500 mA.

See IBUSLIM (REG 14h[6:0])

VIN Input Current Limit (I_{INLIM})

Limits the amount of current drawn from the VIN source. The default setting is 1 A.

See IINLIM (REG 16h[6:0])

Dynamic Input Voltage Control (V_{SOURCE})

Limits the input current when a current–limited weak adapter is connected to either of VBUS or VIN. The settings are configurable from 4.2 V to 8.6 V. The default settings are 4.56 V.

See VBUSLIM (REG 15h[3:0]) and VINLIM (REG 17h[3:0])

CONFIGURABLE BOOST PARAMETERS

The following boost parameters can be programmed by the host through I²C:

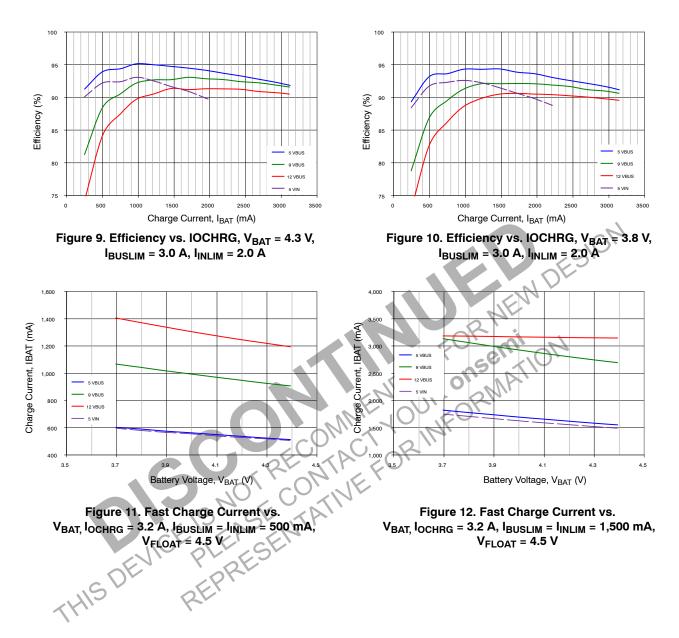
Boost Output Voltage (V_{BOOST})

Regulates the boost converter output voltage on PMID when BOOSTEN = "1". When OTG = "1" VBUS is connected to PMID. The default setting is 5.0 V.

See VBOOST (REG 1Ch[3:0]).

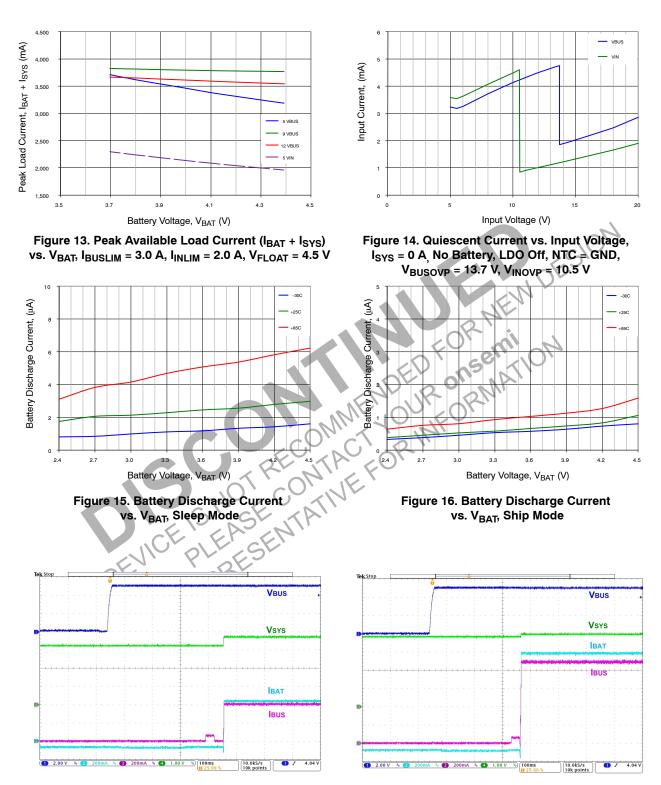
CHARGE MODE TYPICAL CHARACTERISTICS

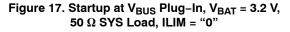
Unless otherwise specified, circuit of Typical Application, using FAN54511A, default register values/settings, $V_{BUS} = 5.0$ V, and $T_A = 25^{\circ}$ C.

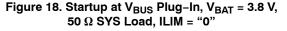


CHARGE MODE TYPICAL CHARACTERISTICS

(Unless otherwise specified, circuit of Typical Application, using FAN54511A, default register values/settings, V_{BUS} = 5.0 V, T_A = 25°C



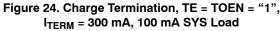




CHARGE MODE TYPICAL CHARACTERISTICS (continued)

(Unless otherwise specified, circuit of Typical Application, using FAN54511A, default register values/settings, V_{BUS} = 5.0 V, and T_A = 25°C)





CHARGE MODE TYPICAL CHARACTERISTICS (continued)

(Unless otherwise specified, circuit of Typical Application, using FAN54511A, default register values/settings, V_{BUS} = 5.0 V, and T_A = 25°C)

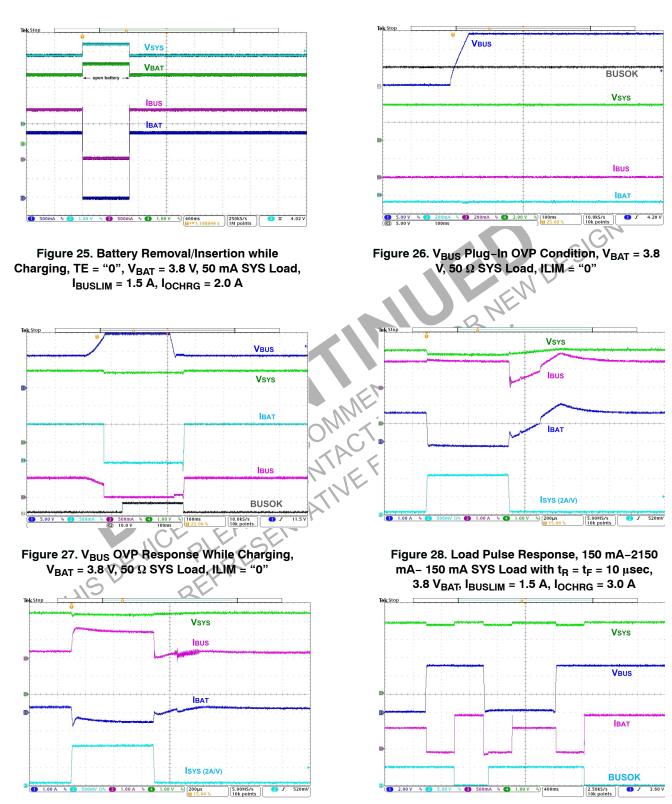


Figure 29. Load Pulse Response, 150 mA-2150 mA- 150 mA SYS Load with $t_R = t_F = 10 \ \mu sec$, 4.35 V_{BAT}, I_{BUSLIM} = 1.5 A, I_{ORCHG} = 3.0 A, TE = "0"

Figure 30. Input Source Selection, 5.0 V_IN Present, Insert/Remove 5.0 V_BUS, 3.8 V_BAT, 50 Ω SYS Load

CHARGE MODE TYPICAL CHARACTERISTICS (continued)

(Unless otherwise specified, circuit of Typical Application, using FAN54511A, default register values/settings, V_{BUS} = 5.0 V, and T_A = 25°C)



Response to SYS Fault, Sleep Mode, 3.8 VBAT

CHARGE MODE TYPICAL CHARACTERISTICS

(Unless otherwise specified, using circuit of Typical Application, V_{BAT} = 3.8 V, V_{BOOST} = 5.00 V, T_A = 25°C. Boost enabled by writing BOOSTEN = OTG = "1", simultaneously.)

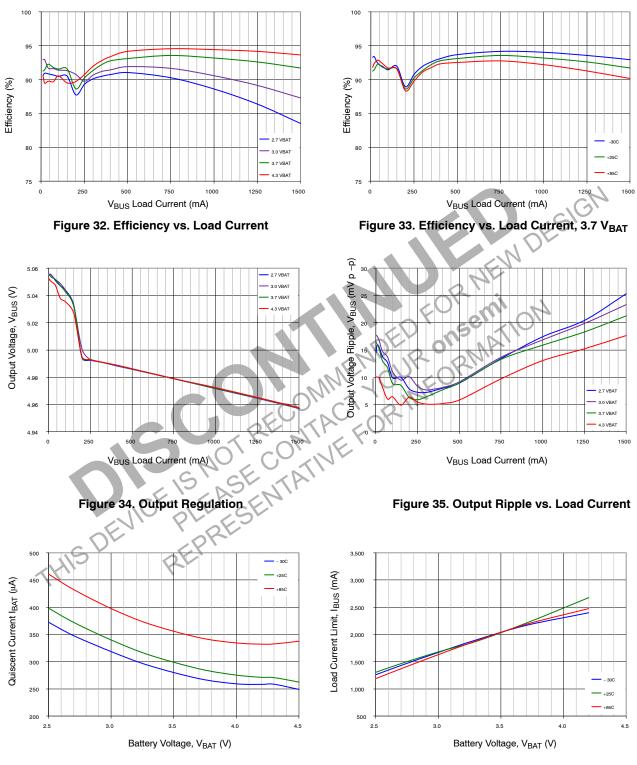
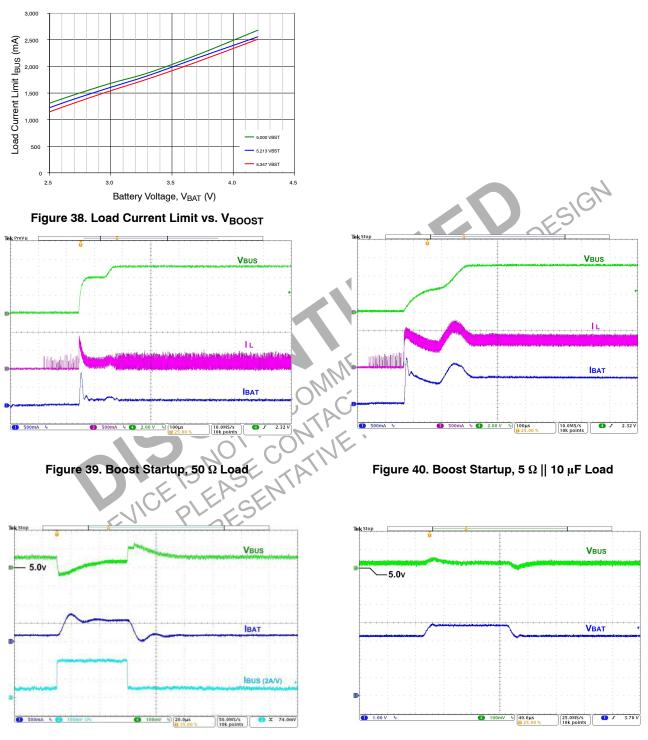


Figure 36. Quiescent Current

Figure 37. Load Current Limit, 5.00 VBOOST

CHARGE MODE TYPICAL CHARACTERISTICS

(Unless otherwise specified, using circuit of Typical Application, V_{BAT} = 3.8 V, V_{BOOST} = 5.00 V, T_A = 25°C. Boost enabled by writing BOOSTEN = OTG = "1", simultaneously.)



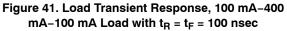


Figure 42. Line Transient Response, 500mA Load, 3.8 V_{BAT} –3.2 V_{BAT} –3.8 V_{BAT} with t_R = t_F = 10 μsec

CHARGE MODE TYPICAL CHARACTERISTICS

(Unless otherwise specified, using circuit of Typical Application, $V_{BAT} = 3.8 \text{ V}$, $V_{BOOST} = 5.00 \text{ V}$, $T_A = 25^{\circ}\text{C}$. Boost enabled by writing BOOSTEN = OTG = "1", simultaneously.)

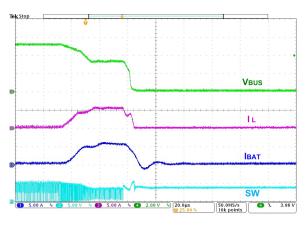


Figure 43. V_{BUS} Output Fault Response

NON-CHARGING STATES

Idle State

During Idle State the PWM Buck continues to regulate system voltage to V_{FLOAT} providing power to the system. The battery is not being charged and the BATFET (Q4) is off.

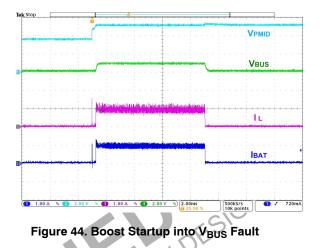
In the Idle State, the V_{BAT}/V_{SYS} comparator is monitored and if V_{SYS} falls below V_{BAT} by V_{THSYS} , the BATFET (Q4) is fully enhanced for Supplemental Mode operation.

If Idle State is entered for any of the following conditions, a return to Charge State occurs when the related condition is removed:

- 1. Charge Complete (CHGCMP = "1") occurs with TE = "1". If RCHGDIS (REG 0Eh[5]) = "0", the IC will return to Charge State when V_{BAT} < V_{FLOAT} – V_{RCHG}.
- 2. The Top-Off Timer (t_{TO}) expires. If RCHGDIS (REG 0Eh[5]) = "0", the IC will return to Charge State when V_{BAT} < V_{FLOAT} - V_{RCHG}.
- 3. The battery is below T1 or above T4. See JEITA Charging section for details.
- 4. The battery is removed and TE = "1".
- 5. The BATFET is disabled by the Charge Enable bit, CE# = "1".

If Idle State is entered for any of the following conditions, the only way to restart charging is to first remove V_{SOURCE} , and then reconnect a valid VIN or VBUS power source:

- The Safety Timer (t_{PRE} or t_{FAST}) expires when CONT (REG 0Eh[7]) = "0".
- 2. The battery voltage drops below V_{SHORT} during charging.
- 3. The Watch Dog Timer (t_{WD}) expires and WDTEXP (REG 30h[7]) = "1".



Standby State

The Standby State is an intermediate state where the PWM Buck is off and the BATFET (Q4) is fully enhanced. During Standby State, reverse current out of the VBUS or VIN pin is prevented by turning off the Q3 and Q5 blocking FETs.

If Standby State is entered for any of the following conditions, a return to Charge State occurs when the related condition is removed:

- 1. Sleep State where $V_{SOURCE} < V_{BAT} + V_{SLP}$ or
 - $V_{SOURCE} < V_{SOURCE(FALL)}$.
- 2. The device has been put in Hi–Z state by
 - HZMODE (REG 0Eh[1]) = "1" or DIS = HIGH.
- 3. The die temperature is in thermal shutdown (T_{SHUTDOWN}).

If Standby State is entered for any of the following conditions, the only way to restart charging is to first remove V_{SOURCE} , and then reconnect a valid VIN or VBUS power source:

1. The USB Timer (t_{USB}) expires (FAN54510A and FAN54512A only).

Sleep State

Sleep State is part of the suite of conditions which make up the Standby State. The BATFET (Q4) is fully enhanced while the IC is in the Sleep State. This ensures that the FAN5451x powers the system from the battery when operating without a valid input source on either VBUS or VIN.

APPLICABLE STATUS AND INTERRUPT

Status Bits: SLEEP (REG 00h[1])

CHARGER CIRCUIT DETAILS

Refer to:

Charger State Diagram" State and Mode Transitions and

Charger State Diagram: Charger/Battery/System Protection

Plug In: Source Selection and Validation

Source Selection

Only one input source (VBUS or VIN) can be routed to the buck converter at any given time. If valid power sources are connected to both VIN and VBUS, the input selector automatically opens Q5 and closes Q3, thereby selecting VBUS as the input source to the buck converter.

The active source is identified by a Status bit.

APPLICABLE STATUS AND INTERRUPT

Status Bits: INPUTSEL (REG 02h[7])

Battery Capacitor Discharge

When either V_{BUS} or V_{IN} rises and remains above $V_{SOURCE(RISE)}$ for the $t_{SRCQUAL}$ (32 mS) duration, the IC applies a I_{DETECT} (-8 mA) load to V_{BAT} for T_{DETECT} (262 ms) to ensure that if the battery is not present, or its discharge protection switch is open, the capacitors on V_{BAT} will be discharged below the V_{SHORT} threshold.

D+/D- Adapter Detection (VBUS only)

See Table 11 and Table 12 for the FAN5451x versions that have this feature.

When V_{BUS} rises and remains above $V_{SOURCE(RISE)}$ for the $t_{SRCQUAL}$ (32 mS) duration, the FAN5451x versions that have this feature perform adapter detection.

SDP, CDP, and DCP adapter types can be uniquely identified by the Charger IC, which will automatically select the appropriate I_{BUS} current limit per the USB Battery Charging Specification (BC1.2), and report the adapter type in a Status register.

APPLICABLE STATUS AND INTERRUPT

Status Bits: CHGDET (REG 01h[6:5]

Source Voltage Validation

After battery capacitor discharge, Source Voltage Validation occurs with a $I_{VSOURCE}$ (50 mA) load on PMID. To pass validation, either V_{BUS} or V_{IN} must remain above $V_{SOURCE(RISE)}$ and below $V_{SOURCEOVP}$ for t_{VSR} VALID (32 ms) before the IC initiates charging. T_{VSR} VALID ensures that unfiltered 50/60 Hz chargers and other non-compliant chargers are rejected.

APPLICABLE STATUS AND INTERRUPT

Pins:	/BUSOK /INOK /INT
Interrupt Bits:	VBUSINT (REG 04h[5]) VININT (REG 04h[6])
Status Bits:	VBUSPWR (REG 00h[5]) VINPWR (REG 00h[6]) INPUTSEL (REG 02h[7])

If the input source fails validation, the validation period is extended an additional 32 ms and source validation is re-tried. A failure will result in an interrupt and the part returning to Sleep State, where the entire validation routine will restart when $V_{SOURCE} > V_{SOURCE(RISE)}$. APPLICABLE STATUS AND INTERRUPT



Battery Voltage Measurement

/INT

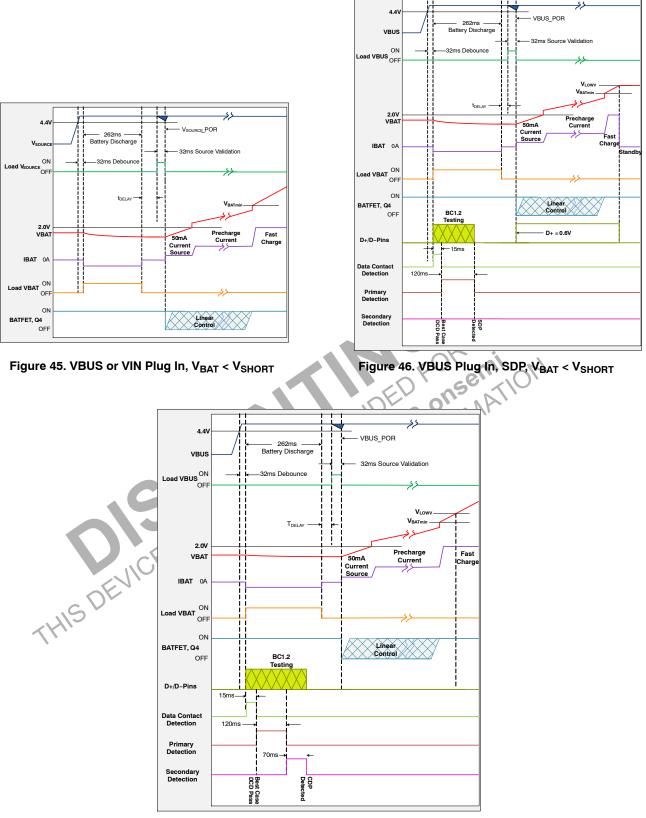
The battery voltage is measured if the adapter passes Source Validation. The IC can identify an absent, shorted, low, or dead battery, configure the charging parameters accordingly, and then enter Charge Mode.

VALFAIL (REG 04h[7])

Figure 45, Figure 46, and Figure 47 illustrate Plug In timing under various conditions. The t_{DELAY} timing specification is affected by V_{BAT} and is described in Table 10.

Table 10. T_{DELAY} TIMING vs. V_{BAT}

V _{BAT} (V)	T _{DELAY} (ms)
< V _{BATMIN}	69
V _{BATMIN} < V _{BAT} < V _{LOWV}	37
> V _{LOWV}	10





CHARGE MODES

Auto-Charge and Establishing Host Control

The FAN5451x features Auto-Charge, which supports battery charging prior to Host Control.

After the source voltage has been validated at Plug In, if $V_{BAT} < V_{BATMIN}$, the IC resets all registers to their default values. Regardless of battery voltage, the IC then operates in accordance with its I²C register settings except that the IBUSLIM (REG 14h[6:0]) settings are ignored until the first I^2C write after charging begins.

Only after the first I²C write after charging begins is Host Control established.

Prior to Host Control, the IBUS current limit and the charge timer length are as described in Table 11 and Table 12.

Once Host Control has been established, the charge parameter settings are as described in Table 13.

For FAN5451x versions where the BC1.2 adapter detection circuit is enabled, the IBUS current limit prior to establishing Host Control is determined by D+/D- Adapter Detection at Plug In. If the adapter type cannot be identified as either CDP or DCP, the charger will be configured to SDP Auto-Charge.

SDP Auto-Charge uses a dedicated SDP timer (t_{USB}) with the I_{BUS} current limit configured as per Table 11. If the t_{USB} timer is allowed to expire, the charger enters Standby State,

where the only way to restart charging is to first remove V_{SOURCE}, then reconnect a valid VIN or VBUS power source.

If a SDP adapter is detected and $V_{BAT} > V_{LOWV}$, the charger will disable the LDO and enter Standby State, where any I²C write to the IC will return it to Charge Mode under Host Control.

If a SDP adapter is detected and the DIS pin is HIGH, the LDO will be disabled after validation and remain disabled until SDP charging occurs when DIS is driven LOW or Host Control is established.

If a CDP or DCP adapter is detected, Auto-Charge uses the Safety Timer with the IBUS current limit set to 1500 mA.

ILIM Pin Control Auto-Charge Mode

See Table 11 and Table 12 for the FAN5451x versions that have this feature.

For FAN5451x versions where the BC1.2 adapter detection circuit is disabled, the ILIM pin is used to set the I_{BUS} current limit prior to Host Control.

ILIM Pin Auto-Charge uses the Safety Timer with the I_{BUS} current limit configured as per Table 11.

the I _{BUS} current limit configured as per Table 11. If the t _{USB} timer is allowed to expire, the charger enters Standby State, Table 11. I_{BUS} CURRENT LIMIT (AUTO-CHARGE ONLY)					
Part Number	Configuration	BC1.2 SDP	BC1,2 CDP/DCP	ILIM Pin Control (ILIM Pin = HIGH)	ILIM Pin Control (ILIM Pin = LOW)
FAN54510A	BC1.2 Detection	500 mA	1500 mA	N/A	N/A
FAN54511A	ILIM Pin Control	N/A	N/A	500 mA	1500 mA
FAN54511AP	ILIM Pin Control	N/A	N/A	500 mA	1500 mA
FAN54512A	BC1.2 Detection	100 mA	1500 mA	N/A	N/A
FAN54513A	ILIM Pin Control	N/A	N/A	100 mA	1500 mA

Table 12. CHARGE TIMER (AUTO-CHARGE ONLY)

Part Number	Configuration	BC1.2 SDP	BC1.2 CDP/DCP	ILIM Pin Control
FAN54510A	BC1.2 Detection	t _{USB} = 2 min.	Safety Timer	N/A
FAN54511A	ILIM Pin Control	N/A	N/A	Safety Timer
FAN54511AP	ILIM Pin Control	N/A	N/A	Safety Timer
FAN54512A	BC1.2 Detection	t _{USB} = 45 min.	Safety Timer	N/A
FAN54513A	ILIM Pin Control	N/A	N/A	Safety Timer

				Charger Bit Settings				
Operating Mode	VSOURCE	VBAT	IINLIM	IBUSLIM	PRECHG	IOCHRG	STAT	PWROK
Linear	Valid	< V _{SHORT}	1000 mA	500 mA	50 mA	Х	1	0
Pre-Charge	Valid	< V _{BATMIN}	1000 mA	500 mA	450 mA	Х	1	0
FAST Charge	Valid	> V _{BATMIN}	1000 mA	500 mA	Х	1000 mA	1	0
FAST Charge	Valid	> V _{LOWV}	1000 mA	500 mA	Х	1000 mA	1	1
Top-Off	Valid	> V _{LOWV}	1000 mA	500 mA	Х	1000 mA	0	1
Recharge	Valid	> V _{LOWV}	1000 mA	500 mA	Х	1000 mA	1	1

Table 13. CHARGE PARAMETER SETTING VS. OPERATING MODE (HOST CONTROL ONLY)

Linear Pre-Charge Mode

At the beginning of charging, if $V_{BAT} < V_{SHORT}$, the BATFET (Q4) operates as a linear current source with its current limited to 50 mA (I_{SHORT}) in order to safely recover a battery pack with an open protection switch. Additionally, the IC delivers power to SYS by regulating V_{SYS} to the default VSYS (REG 0Dh[1:0]) setting.

Pre-Charge (IPP) Mode

At the beginning of charging, if $V_{SHORT} < V_{BAT} < V_{BAT}$, or if V_{BAT} has transitioned above V_{SHORT} from Linear Pre-Charge Mode, the IC enters Pre-Charge Mode while delivering power to SYS.

During Pre-Charge Mode, the BATFET (Q4) will operate as a linear current source with its current limited to the PRECHG (REG 13h[3:0]) setting. The IC will regulate V_{SYS} to the VSYS (REG 0Dh[1:0]) setting and attempt to charge the battery at less than or equal to the PRECHG setting without allowing V_{SYS} to drop below V_{BATMIN} .

All registers are programmable in Pre-Charge Mode. APPLICABLE STATUS AND INTERRUPT

/STAT

Pins: Interrupt Bits: Status Bits:

WKBAT (REG 04h[1] PRE (REG 00h[2]) STAT (REG 00h[3])

Fats Charge (I_{OCHRG}) Mode

At the beginning of charging, if $V_{BAT} > V_{BATMIN}$, or if V_{BAT} has transitioned above V_{BATMIN} from Pre-Charge Mode, the IC enters Fast Charge.

During Fast Charge Mode, the BATFET (Q4) is fully enhanced and acts as a current sense element to limit charge current per the IOCHRG (REG 12h[5:0]) setting. Battery charging under constant current (CC) I_{OCHG} control continues until the battery voltage reaches V_{FLOAT} . APPLICABLE STATUS AND INTERRUPT

Pins:	/INT /STAT
Interrupt Bits:	CHGMOD (REG 04h[2])

Good Battery Threshold (VLOWV)

The VLOWV (REG 0Ch[5:3]) bits define a battery voltage threshold between 3.0 V and 3.7 V where an interrupt is generated. The system designer can use this interrupt to indicate that full system power is available or for any other purpose. Charge parameters are not affected by VLOWV.

APPLICABLE STATUS AND INTERRUPTS

Pins: /INT Interrupt Bits: VLOWVTH (REG 04h[4])

Status Bits: PWROK (REG 00h[4])

Constant Voltage (CV) Mode

When V_{BAT} reaches V_{FLOAT} , as set by VFLOAT (REG 11h [7:0]), the charger enters the voltage regulation (CV Mode) phase of charging. The PWM regulator goes from regulating current across the BATFET (Q4) to regulating voltage on the BATSNS pin. This results in charge current declining.

The CV (REG 20h[0]) Monitor bit will be set to a "1" while the IC is in CV Mode.

Termination

Charge current termination is enabled when TE (REG 0Eh[3]) = "1". When charge current falls below I_{TERM} , as set by ITERM (REG 13h[7:6]), for longer than the deglitch time of 30 ms, charging stops, Q4 turns off, an interrupt is issued, and the IC enters Idle State (Charge Complete) if TOEN (REG 0Eh[2]) = "0". The buck converter will regulate SYS to VFLOAT (REG 11h[7:0]) and the battery will support Supplemental Mode if required.

Recharge occurs after Termination (TE = "1"), if RCHGDIS (REG 0Eh[5]) = "0", when $V_{BAT} < V_{FLOAT} - V_{RCHG}$.

Charge termination is blocked unless the I_{TERM} threshold is crossed while in CV Mode. If another control loop (IBUSLIM, IOCHRG, DIVC) or Supplemental Mode operation exist, termination will be prevented until the CV condition is met.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT /STAT
Interrupt Bits:	CHGEND (REG 04h[3])
Status Bits:	CHGCMP (REG 01h[4])

If TE = "0", when the charge current falls below I_{TERM} , charging continues, an interrupt is issued, but the CHGCMP bit is not set.

APPLICABLE STATUS, INTERRUPT AND MONITOR

Pins:	/INT
Interrupt Bits:	IBATLO (REG 05h[7])
Status Bits:	LOIBAT (REG 01h[7])
Monitor Bits:	ITERMCMP (REG 20h[7])

Top-Off Charging Mode

Top-Off Charging occurs after Termination (TE = "1") if TOEN (REG 0Eh[2]) = "1". The CHGEND interrupt will be issued and Top-Off Charging begins 400 ms later with the /STAT pin HIGH. During Top-Off Charging, the Battery Absence Detection is retried every 5s unless TO_BDETDIS (REG 1Bh[3]) is set to "1".

The Top-Off Charging duration is set by the Top-Off Timer, TOTMR (REG 1Bh[2:0]). See Top-Off Timer for details.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT STAT
Interrupt Bits:	CHGEND (REG 04h[3]) TOCMP (REG 06h[7])
Status Bits:	STAT (REG 00h[3]) LOIBAT (REG 01h[7]) TOCHG (REG 01h[3])

System Current Prioritization

During Charge Mode, if the current available to charge is less than the programmed charge setting due to an input current limit setting, source limitations, or system load requirements, the current to the battery will be reduced to support the system load.

Supplemental Mode

During Charge Mode or Idle State, if the system load exceeds what the buck converter can provide, V_{SYS} will drop. If a falling V_{SYS} drops more than V_{THSYS} below V_{BAT} , the BATFET (Q4) will be fully enhanced to hold the system up to V_{BAT} .

Then, once a rising V_{SYS} becomes higher than V_{BAT} by V_{THSYS} , the BATFET (Q4) again serves as the current sense element to limit the charge current.

PWM	Operating Mode	CE#	VSOURCE	VBAT	BATFET (Q4)
OFF	SLEEP	х	Both < (VSYS + VSLP)	NF x	ON
ON	Linear and Pre-Charge	0	Valid	> VSHORT & < VBATMIN	Linear
ON	FAST Charge	0	Valid	> VBATMIN & < VSYS	ON
OFF	HZMODE (REG 0Eh[1]) = "1"	Ň,		Х	ON
ON	Supplemental	X	Valid	> VSYS	ON
ON	CE# = "1" (disable Q4 with Supplemental Mode remaining functional)	A S	EM Valid	< VSYS	OFF
ON	PPOFF = "1" (disable Q4 with Supplemental Mode disabled)	x	Valid	Х	OFF

Table 14. SUMMARY OF BATFET (Q4) OPERATION VS. OPERATING MODE

Source Plug Out

The IC continuously monitors V_{BUS} (or V_{IN}) during charging. If V_{SOURCE} falls below the higher of $V_{SOURCE(FALL)}$ or $V_{BAT}+V_{SLP}$ the IC terminates charging and enters Sleep State (Standby).

APPLICABLE STATUS AND INTERRUPT

Pins:	/BUSOK /INOK /INT /STAT
Interrupt Bits:	VLOWTH (REG 04h[4]) VBUSINT (REG 04h[5]) VININT (REG 04h[6])
Status Bits:	SLEEP (REG 00h[1]) VBUSPWR (REG 00h[5]) VINPWR (REG 00h[6]) INPUTSEL (REG 02h[7])

CHARGING STATUS AND INTERRUPT REPORTING

Charging Status

The /STAT pin is used to report the charge status to the host processor. During charge, the /STAT pin is LOW. After Termination, the /STAT pin goes HIGH and will remain HIGH even during Top–Off Charging Mode.

The STAT (REG 00h[3]) bit indicates a "1" when charging except during Top–Off.

APPLICABLE STATUS AND INTERRUPT

Pins:	/STAT
Status Bits:	STAT (REG 00h[3])

Interrupts

The /INT pin is used to indicate that one or more unmasked interrupt bits have been set.

The pin will remain LOW until all set interrupt bits (Registers 04h to 06h) are read and cleared. In the event that another interrupt occurs while the register containing the bit is read, the interrupt will be stored in a buffer and transferred to the register after the read. Thus, the /INT pin may remain LOW until the register is read and cleared again.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT
Interrupt Bits:	INT 0 (REG 04h) INT 1 (REG 05h) INT 2 (REG 06h)

Interrupt Masking

Masking an interrupt bit using its corresponding mask bit, found in registers 08h to 0Ah, prevents a masked interrupt event from setting the /INT pin to LOW. The associated interrupt bit will be set to "1".

CHARGER/BATTERY/SYSTEM PROTECTIONS

Dynamic Input Voltage Control

The IC includes a Dynamic Input Voltage Control (DIVC) loop which automatically limits input current in case a current–limited source is supplying V_{BUS} or V_{IN} . The control loop increases the charging current until either: I_{BUSLIM} / I_{INLIM} or I_{OCHRG}

is reached or

 $V_{BUS} = V_{BUSLIM}$ or $V_{IN} = V_{INLIM}$

If an increase in load occurs on VSYS during charging that causes VBUS or VIN to reduce below VBUSLIM or VINLIM, the charge current is reduced until VBUS or VIN rise to the VBUSLIM or VINLIM threshold. At V_{SOURCE} plug in, the VBUSLIM (REG 15h[3:0]) and VINLIM (REG 17h[3:0]) bits are always set to their default values.

High-Impedance Mode and Disable

Setting the HZMODE (REG 0Eh[1]) bit to "1" or setting the DIS pin to HIGH disables the charger and puts the IC into High–Impedance Mode (HZ). The Safety Timer and Watch Dog Timer are reset.

If V_{BAT} falls below V_{BATMIN} , with HZMODE set to "1", the HZMODE bit will automatically reset to "0", and charging will commence. Setting HZMODE = "1" when $V_{BAT} < V_{BATMIN}$ is ignored. The DIS pin is functional when $V_{BAT} < V_{BATMIN}$.

Safety Timer

At the beginning of charging, the IC starts the Safety Timer. The Safety Timer consists of two segments, Pre-Charge (PRETMR) and Fast Charge (FCTMR). The Safety Timer can be programmed using the bits in the FIMER (REG 19h) register.

The Pre-Charge timer begins at the start of charging of a battery whose voltage is less than V_{BATMIN} . Once the battery voltage has risen above V_{BATMIN} , the Pre-Charge Timer is cleared and the Fast Charge Timer begins. If the battery voltage were to fall below V_{BATMIN} during Fast Charge, the Fast Charge Timer will continue to run until the battery is fully charged or the timer expires.

Charging with the Safety Timer running is used for charging that is unattended by the host. If the Safety Timer expires charging ceases, all registers reset to their default values, the device enters Idle State, and an interrupt is issued.

If the CONT (REG 0Eh[7]) = "1", charging will continue if the Safety Timer is allowed to expire.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT /STAT
Interrupt Bits:	TIMER (REG 06h[0])
Status Bits:	TMRTO Status bit (REG 02h[0])

Watch Dog Timer (WDT)

Setting WDEN (REG 19h[6]) to "1" enables the WDT and disables, but does not clear the Safety Timer.

Setting TMRRST (REG19h[7]) to "1" resets the WDT. This bit should be written at a rate more frequent than t_{WD} .

If the WDT expires, charging continues on the remainder of the time left on the Safety Timer. Additionally, all registers except SAFETY (REG 1Ah[7:0]), are reset to their default values, and an interrupt is issued. If WDTEXP (REG 30h[7]) = "1" and the WDT expires, the device will instead immediately enter Idle State.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT /STAT
Interrupt Bits:	TIMER (REG 06h[0])
Status Bits:	WDTTO (REG 02h[1])

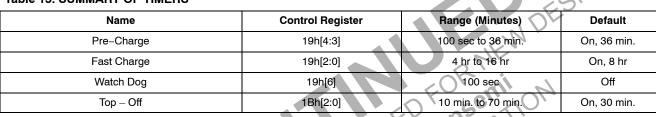
Table 15. SUMMARY OF TIMERS

Top-Off Timer

The Top–Off timer duration is programmable using the TOTMR (REG 1Bh [2:0]) bits. When the timer expires charging stops, the BATFET (Q4) is disabled, an interrupt is issued, and the device enters Idle State. If RCHGDIS (REG 0Eh[5]) = "0", the IC will return to Charge State when $V_{BAT} < V_{FLOAT} - V_{RCHG}$.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT
Interrupt Bits:	TOCMP (REG 06h[7])
Status Bits:	CHGCMP (REG 01h[4])



Thermal Regulation

When the IC's junction temperature reaches the programmable Thermal Regulation threshold, T_{REGTH} , set by TREGTH (REG (0Fh[6:5]), the thermal regulation loop reduces charge current to the lowest IOCHRG (REG 12h[5:0]) setting (200 mA) to prevent overheating.

The device will attempt to charge the battery at a maximum average current while maintaining the die temperature at or below T_{REGTH} . This is accomplished by stepping I_{OCHRG} from the lowest IOCHRG setting back up to the programmed IOCHRG setting. If T_{REGTH} is again reached the process is repeated.

During Thermal Regulation, the IBUSLIM and IINLIM input current limit settings are retained in order to support the system load from a valid power source.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT
Interrupt Bits:	ICTEMP (REG (06h[4])
Status Bits:	TEMPFB (REG 02h[4])

Thermal Shutdown

If the junction temperature increases beyond the Thermal Shutdown threshold, $T_{SHUTDOWN}$, charging is suspended and the buck converter is disabled. While suspended, all timers stop and registers do not reset. Charging resumes only after the die temperature falls below T_{REGTH} where I_{OCHRG} will be stepped back up to the programmed IOCHRG setting.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT /STAT
Interrupt Bits:	ICTEMP (REG (06h[4])
Status Bits:	TEMPSD (REG (02h[5])

Register Reset Conditions

As an added layer of safety, the I²C control bits automatically reset to their default values under certain situations. Refer to Table 16 for details.

Table 16. REGISTER RESET SUMMARY

Reset Condition Description	Registers that are Reset	Behavior After Reset Event
VBUS/VIN plug in (from no input connected) and any V_{BAT} voltage	VBUSLIM and VINLIM only	VBUSLIM = 4.56 V VINLIM = 4.56 V
VBUS/VIN plug in (from no input connected) and V_{BAT} < V_{SHORT}	All registers <u>except</u> STATUS, and IN TERRUPT	Pre-Charge with default settings; Q4 in Linear Region
VBUS/VIN plug in (from no input connected) and V_{SHORT} < V_{BAT} < V_{BATMIN}	All registers <u>except</u> SAFETY, STATUS, and INTERRUPT	Pre-Charge with default settings; Q4 in Linear Region
V_{BAT} falls below V_{BATMIN} with an input connected	HZMODE bit only	Pre-Charge at programmed settings; Q4 in Linear Region
Battery Removal Detected (input connected)	VFLOAT, IOCHRG, PRECHG, ITERM, SAFETY	Buck regulates at V _{FLOAT} ; Q4 Off
Pre-Charge / Fast Charge Safety Timer Ex- piration		Buck regulates at 4.35 V; Charging stops; Q4 Off
Charge Mode Watchdog Timer Expiration (WDTEXP="0")	All registers <u>except</u> SAFETY, STATUS, and INTERRUPT	Charging continues with default settings; Q4 On
Charge Mode Watchdog Timer Expiration (WDTEXP= "1")		Buck regulates at 4.35 V; Charging stops; Q4 Off
OTG Boost Mode Watchdog Timer Expira- tion		Boost Off; Q3 Off; Q4 On
Set RESET (REG 0Fh[7]) = "1" (Charge Mode)		Charging continues with default settings; Q4 On
Set RESET (REG 0Fh[7]) = "1" (OTG Boost Mode)	MENUP	Boost Off; Q3 Off; Q4 On

JEITA Charging

The IC reduces I_{OCHRG} and V_{FLOAT} if the measured battery temperature is outside of the fast charging limits (Between T2 to T3) as described in the JEITA specification. There are four battery temperature thresholds that change battery charger operation: T1, T2, T3, and T4.

The IC first measures the NTC immediately prior to entering any PWM charging state, and then measures the NTC once per second, updating the result in the NTC4–NTC1 bits (REG 18h[3:0]).

The Host processor can disable JEITA charging reduction by setting the TEMPDIS (REG 18h[5]) bit to "1".

To disable the thermistor circuit, tie the NTC pin to GND. This also disables the REF output. Before enabling the charger, the IC tests to see if NTC is shorted to GND. If NTC is shorted to GND, the NTCGND monitor bit (REG 21h[2]) will be set, no thermistor readings will take place, the NTCOK bit (REG 18h[4]) and NTC4–NTC1 (REG 18h[3:0]) bits will be reset.

APPLICABLE STATUS AND INTERRUPTS

Pins:	/INT
Interrupt Bits:	BATTEMP (REG 06h[3])
Status Bits:	JEITA (REG 02h[3]) TBAT (REG 02h[2])

Table 17. BATTERY TEMPERATURE THRESHOLDS, FOR USE WITH 10 K NTC, B = 3380, and $R_{REF} = 10$ K

Threshold	T _{BAT} (°C)	% of VREF
T1	0°C	73.9
T2	10°C	64.6
Т3	45°C	32.9
T4	60°C	23.3

T _{BAT} (°C)	IOCHRG	V _{FLOAT}	NTC4-1	JEITA	TBAT	Notes
Below T1	Charging d	isabled (Q4 open)	0000	1	1	
Between T1 and T2	I _{OCHRG} / 2	V _{FLOAT} – 200 mV	0001	1	0	If IOCHRG is programmed to less than 400 mA, the charge current will be limited to 200 mA.
Between T2 and T3	IOCHRG	V _{FLOAT}	0011	0	0	
Between T3 and T4	I _{OCHRG} / 2	V _{FLOAT} – 200 mV	0111	1	0	If IOCHRG is programmed to less than 400 mA, the charge current will be limited to 200 mA.
Above T4	Charging d	isabled (Q4 open)	1111	1	1	

Table 19. TEMPERATURE THRESHOLD WITH VARIOUS THERMISTORS,	R _{REF} = R _{THRM} AT 25 °C
-----------------------------------------------------------	-----------------------------------------------

Parameter		Various Thermistors	310
R _{THRM(25°C)}	10K	10K 47K	100K
β	3380	3940 4050	4250
T1	0°C	3°C 6°C	8°C
T2	10°C	12°C 13°C	14°C
Т3	45°C	42°C 41°C 41°C	40°C
T4	60°C	55°C 53°C	51°C

Pin

V_{BUS} Over–Voltage Protection

When $V_{BUS} > V_{BUSOVP}$, the IC stops switching, fully enhances Q4 to support SYS load, and issues an interrupt.

When V_{BUS} falls below V_{BUSOVP} - V_{BUSOVP(HYS)}, charging resumes after VBUS is revalidated, where another interrupt is issued.

If $V_{BUS} > V_{BUSOVP}$ VIN cannot be used as a charging source.

APPLICABLE STATUS AND INTERRUP

BUSOK Pins: /INT /STAT VBUSINT (REG 04h[5]) Interrupt Bits: OVPINPUT (REG 06h[6]) Status Bits: INPUTOVP (REG 02h[6])

VIN Over-Voltage Protection

When $V_{IN} > V_{INOVP}$, the IC stops switching, opens Q5, fully enhances Q4 to support SYS load, and issues an interrupt.

When V_{IN} falls below $V_{INOVP} - V_{INOVP(HYS)}$, charging resumes after VIN is revalidated, where another interrupt is issued.

If $V_{IN} > V_{INOVP}$, VBUS cannot be used as a charging source.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INOK /INT /STAT
Interrupt Bits:	VININT (REG 04h[6]) OVPINPUT (REG 06h[6])
Status Bits:	INPUTOVP (REG 02h[6])

VBAT Over-Voltage Protection

The FLOAT voltage regulation loop prevents V_{BAT} from overshooting VFLOAT by more than VBAT OVP if the battery is removed during Charge Mode with TE(REG 0Eh[3]) ="0" or "1".

Additionally, if the battery is removed during Charge Mode and TE = "0", the IC will remain in Charge Mode. Then if a battery is inserted that is charged to a voltage higher than 1.05 * V_{FLOAT};

- 1. PWM pulses stop while $V_{BAT} > V_{FLOAT}$.
- 2. HIVBAT (REG 20h[3]) monitor bit set to "1".
- 3. BATFET (Q4) remains on to support the
- system, thus removing excess charge from the battery.

Battery Absence Detection while Charging

The IC can detect the presence, absence, or removal of a battery if TE (REG 0Eh[3]) = "1" and CE# = "0". During normal charging, once $V_{BAT} = V_{FLOAT}$ and the charge current falls below I_{TERM} , the PWM charger continues to provide power to SYS, the BATFET (Q4) is turned off except to support Supplemental Mode, and the IC enters Idle State. It then turns on a battery discharge current, I_{DETECT} , for t_{DETECT}. If V_{BAT} is still above $V_{FLOAT} - V_{RCHG}$, the battery is present and the NOBAT bit is maintained at "0". If V_{BAT} is below $V_{FLOAT} - V_{RCHG}$, the battery is absent and the IC resets all charging related registers to their default values (FLOAT, IOCHRG, PRECHG, and ITERM) and issues an interrupt.

By default the IC will retry Battery Absence Detection every t_{INT} (2.1 s) unless NOBATOP (REG 0Eh[4]) = "0". APPLICABLE STATUS AND INTERRUPT

Pins:	/INT
Interrupt Bits:	BATINT (REG 04h[0])
Status Bits:	NOBAT (REG. 00h[0])

Battery Under-Voltage Protection

The battery voltage falling below V_{SHORT} during battery charging indicates that a catastrophic event has occurred on the BAT pin. If the battery voltage drops below V_{SHORT} during charging, the IC will automatically disable the BATFET (Q4) to stop current flow to the battery node, and issue an interrupt. The IC enters the Idle State where the buck converter continues to provide power to the system. If the battery voltage recovers above V_{SHORT} , Q4 remains off (Idle State is maintained) and BATSHORT is set to "1". This implementation is intended to lock out battery charging. The only way to restart charging is to first remove V_{SOURCE} , and then reconnect a valid VIN or VBUS power source. **APPLICABLE STATUS AND INTERRUPT**

Pins:/INT
/STATInterrupt Bits:SHORTBAT (REG 06h[5])Status Bits:LOIBAT (REG 01h[7])Monitor Bits:BATSHORT (REG 20h[4])

BATFET (Q4) Over-Current Protection

In order to prevent damage to the charger and battery due to a potentially dangerous fault on the SYS pin, the IC prevents its internal BATFET(Q4) from allowing excessive battery discharge current for more than T_{SCQUAL} . The Q4 short circuit current limit ($I_{LIMQ4SC}$) is set for 9 A (typical). If the battery is connected and the discharge current through Q4 exceeds $I_{LIMQ4SC}$ for more than the t_{SCQUAL} deglitch time (1 ms), Q4 will be disabled for the $t_{SCRECOV}$ recovery time of 2 seconds. Once the 2 seconds has passed, Q4 will turn on and check if the over–current condition still exists. If the over–current condition still exists, Q4 will be disabled again for 2 seconds. This cycle will repeat until the over–current condition is removed.

APPLICABLE STATUS AND INTERRUPT

Pins: /INT Interrupt Bits: BATOCP (REG 06h[1])

Safety Register

The IC contains a SAFETY (REG 1Ah) register that prevents the values in FLOAT (REG 11h[7:0]) and IOCHRG (REG 12h[5:0]) from being set to unsafe levels. The VSAFE (REG 1Ah[7:4]) and ISAFE (REG 1Ah[3:0]) register bits within the SAFETY register set a maximum programmable value for FLOAT and IOCHRG.

After V_{BAT} rises above V_{SHORT} , the SAFETY register is loaded with its default value and may be changed on the first write to the SAFETY register and only before writing to any other register. The VSAFE and ISAFE values must be written to the register at the same time. After first writing to the SAFETY register or any other register, the SAFETY register is locked.

The SAFETY register will reset to default values when $V_{BAT} < V_{SHORT}$. The SAFETY register does not reset if the Safety Timer or WDT timer expires.

Ship Mode

Ship Mode is a state where the BATFET (Q4) is configured to isolate the battery from the system load to minimize battery discharge current to the system. This mode of operation is useful for preserving the battery life of a mobile device during extended shipping and storage durations. Ship Mode is also useful for production testing of a mobile device without having to drain the battery.

The /SHIP pin controls entry into and exit out of Ship Mode. To enter Ship Mode, the /SHIP pin must be held LOW for $t_{SHIPENTER}$. To exit Ship Mode, /SHIP must be first released and then held LOW for $t_{SHIPEXIT}$. This configuration prevents accidental entry into and exit out of Ship Mode with a single key press of a mobile device's power button. An alternate method for exiting Ship Mode is to reapply a valid source to VBUS or VIN. Once the source has been validated, the charger IC will exit Ship Mode.

Ship Mode can also be programmed using the PPOFF (REG 0Fh[1]) and PPOFFSLP (REG 0Fh[2]) control bits. Setting PPOFF to "1" will disable Q4 and isolate the battery from the system load. As long as there is input power to maintain the charger's I²C port, setting PPOFF back to "0" will re–enable Q4.

Setting PPOFFSLP to "1" while there is input power connected will disable Q4 once power is removed from VBUS and VIN. Once power is reapplied, the charger IC will automatically enable Q4.

The PPOFF and PPOFFSLP bits are automatically controlled by the /SHIP pin. When entering Ship Mode using the /SHIP pin, PPOFF and PPOFFSLP are set to "1". When exiting Ship Mode using the /SHIP pin, PPOFF and PPOFFSLP are reset to "0".

Hardware Reset

This is a factory configurable option of the /SHIP pin.

The Ship Mode feature can be disabled and the /SHIP pin can also be reconfigured to perform a Hardware Reset. When the /SHIP pin is held LOW for 8 s it will disable Q4 for 512 ms and discharge SYS using an internal 200 Ω pull-down. After the 512 ms period has passed, Q4 is re-enabled and the 200 Ω pull-down is disconnected from SYS. This feature allows for a quick system restart of a mobile device with an embedded battery by eliminating the time needed for the battery to self-discharge to the point where its protection switch opens.

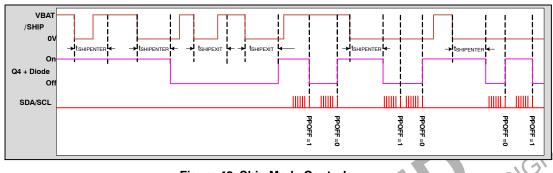


Figure 48. Ship Mode Control

BOOST CIRCUIT DETAILS

Refer to: Boost State Diagram

Q1 and Q2 operate as a synchronous boost regulator to provide power to the VBUS pin for USB-On-the-Go (OTG) applications using the battery as its input. The Boost output voltage can be programmed using the VBOOST (REG 1Ch[3:0]) bits.

Boost Enable and Programming

Boost Mode can be enabled by setting the BOOSTEN (REG 1Ch[5]) bit to "1". BOOSTEN starts the boost operation, regulating VBOOST (REG1Eh[3:0]) at the PMID node. To provide power out to the VBUS pin, the OTG bit (REG 1Ch[6]) must also be set to "1". Whenever boost mode is disabled, either by a fault or writing BOOSTEN="0", the OTG bit will be automatically reset to "0".

The HZMODE (REG 0Eh[1]) bit will be ignored when the boost is enabled. The device will return to High Impedance Mode when BOOSTEN is set back to "0" or the DIS pin is raised HIGH.

The boost should not be enabled with a valid VIN present.

If a source is plugged into VIN while the boost is already running, VIN will be ignored (Q5 will remain off) until the boost is disabled.

Boost Mode and Timer Operation

It is recommended to enable the watchdog timer (t_{WD}) by setting WDEN (REG 19h[6]) bit to "1" to ensure that the host processor is controlling Boost Mode operation. The TMRRST (REG 19h[7]) bit must be set by the host before the t_{WD} timer times out. If t_{WD} times out in Boost Mode, the BOOSTEN and OTG bits are reset, and an interrupt is issued. APPLICABLE STATUS AND INTERRUPT

 Pins:
 /INT

 Interrupt Bits:
 BSTWDTTO (Reg.05h[1])

 Status Bits:
 BOOST (REG 01h[1])

Boost PWM Control

The IC uses a computed off-time and a regulated on-time (with an enforced minimum) to regulate V_{PMID} . The regulator achieves excellent transient response by employing current-mode modulation.

Since V_{BOOST} is regulated at the PMID node, V_{BUS} will exhibit a load-line equal to the $R_{DS(ON)}$ of Q3.

Boost PFM Mode

If $V_{PMID} > VREF_{BOOST}$ (nominally 5.00 V) when the minimum off-time has ended, the regulator enters PFM Mode. Boost pulses are inhibited until $V_{PMID} < VREF_{BOOST}$. The minimum on-time is increased to enable the output to pump up sufficiently with each PFM boost pulse. Therefore the regulator behaves like a constant on-time regulator, with the bottom of its output voltage ripple at V_{BOOST} in PFM Mode.

Boost Startup

As the device should be in the Standby State when the boost is enabled, the BATFET (Q4) will already be enabled to support the system.

Soft-Start State

By setting BOOSTEN = "1", the boost regulator begins switching with a reduced peak current limit of 50% of its normal current limit (ILIMPK(BST)). The output slews up until V_{PMID} is within 5% of its setpoint (V_{BST}); at which time, the regulation loop is closed and the current limit is set to 100%.

If the output fails to achieve 95% of its setpoint within 128 µs, the current limit is increased to 100%. If the output fails to achieve 95% of its setpoint after an additional 1 ms period, a boost fault state is initiated and an interrupt is issued.

APPLICABLE STATUS AND INTERRUPT

Pins: /INT Interrupt Bits: BSTFAIL (Reg.05h[3])

Short Check State

The OTG (REG 1Ch[6]) control bit needs to be set in order to pass the boost output voltage (PMID) to VBUS for USB On-the-Go operation. Once OTG is set to "1", the Short Check state enables a resistor from PMID to V_{BUS} and waits for V_{BUS} to rise to about 1.5 V before proceeding with the VBUS Connect State. This prevents high current drain from the battery, which could occur if Q3 is turned on into a short. circuit.

If V_{BUS} fails to rise above 1.5 V within 8 ms, an interrupt is issued, the resistor is disconnected between PMID and VBUS, and VPMID remains regulated to VBOOST.

APPLICABLE STATUS AND INTERRUPT

Pins:	

/INT OTGOCP (REG 06h[2]) Interrupt Bits:

If the VBUS fault is removed, Short Check State will automatically retry after 2 seconds, and then proceed to the **VBUS** Connect State

VBUS Connect State

If a short is not detected on V_{BUS} during the Short Check State, Q3 will fully turn on and provide a low impedance path between PMID and VBUS. The resistor between PMID and VBUS is left connected. This state ends when VBUS rises above V_{PMID}-400 mV within a 1 ms period, at which point boost regulation is achieved and a Status bit is set.

APPLICABLE STATUS AND INTERRUPT

Status Bits: BOOST (REG 01h[1])

If V_{BUS} fails to reach V_{PMID}-400 mV within 1 ms, a boost fault state is initiated, and an interrupt is issued.

APPLICABLE STATUS AND INTERRUPT

Pins:	/INT
Interrupt Bits:	BSTFAIL (REG 05h[3])

Boost State

This is the normal operating mode of the boost regulator.

ΥN

The minimum t_{OFF} is proportional to V_{OUT} , which keeps the regulator's switching frequency relatively constant in CCM.

Boost Alert

When the battery voltage falls below 3.0 V an interrupt is issued warning that the battery is depleted. The /INT pin is pulled low to alert the processor of the condition. BOOSTEN is not reset.

APPLICABLE STATUS AND INTERRUPT

Interrupt Bits: VBATLV (REG 05h[0]) BATLO (REG 01h[0]) Status Bits:

/INT

Boost Faults

Pins:

If a BOOST fault occurs:

The /INT Pin is pulled low for Interrupt faults.

2. BOOSTEN bit is reset to "0". OTG bit is reset to "0". Q3 is opened.

3. BOOST status bit is cleared.

4. The power stage is in High–Impedance Mode.

5. Interrupt bits are set per Table 20.

BOOSTEN is reset on boost faults. Boost Mode can only be re-enabled by setting the BOOSTEN bit.

Boost Shutdown

When the boost regulator is shut down (BOOSTEN = "0"), current flow is prevented from VBAT to VBUS, as well as reverse flow from V_{BUS} to V_{BAT} .

Fault Name	Fault Bit	Fault Description
BSTOVP	REG 05h[5]	$V_{PMID} > V_{BOOST_OVP}$
BSTFAIL	REG 05h[3] V _{PMID} fails to achieve the voltage required to advance to the next state during or sustained (> 50 μs) current limit during the BST state.	
BATUVL	REG 05h[2]	V _{BAT} < UVLO _{BST}
BSTTSD	REG 05h[4]	Thermal Shutdown (T > T _{REGTH})
BSTWDTTO	REG 05h[1]	Boost Watch Dog Timer Fault

LDO

The FAN5451x provides a 4.95 V (typical), 10 mA LDO that is sourced by PMID. The LDO is automatically enabled 32 ms after V_{BUS} or V_{IN} Plug In.

The LDO can be disabled by setting LDO OFF (REG 0Dh[5]) to "1". The LDO output voltage can be programmed using the VLDO (REG 0Dh[4:3]) bits.

Whenever the FAN5451x is operating in boost mode (BOOSTEN = "1"), the LDO will be disabled. When the LDO is disabled, an internal switch pulls the output low through a 1.2 k Ω pull-down resistor.

LDO and GPO Configurations

FAN54511A, FAN54511AP, FAN54513A only

The LDO output sources the high side of the GPO1 and GPO2 CMOS output drivers, while the gate of the output drivers are controlled by the GPO2 (REG 0Dh [7]) and GPO1 (REG 0Dh [6]) control bits. LDO and GPO1 are enabled by default.

I²C INTERFACE

The FAN5451x's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I2C bus specifications. The FAN5451x's SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls low during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 21. I²C Slave Address Byte

7	6	5	4	3	2	4	
1	1	0	1	0	710	SY,	R/W

In hex notation, the slave address assumes a "0" LSB. The hex slave address is D6H (8-bit write address) for all parts in the family. Other slave addresses can be accommodated upon request. Contact your ON Semiconductor representative.

Bus Timing

As shown in Data Transfer Timing, data is normally transferred when SCL is low. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

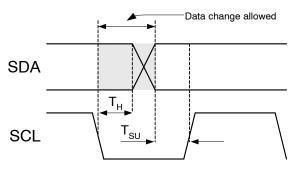
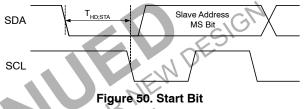
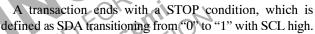


Figure 49. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH.





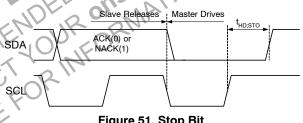


Figure 51. Stop Bit

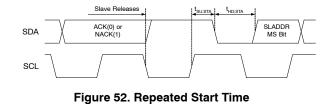
During a read from the FAN5451x, the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0 transition on SDA while SCL is high.

High-Speed (HS) Mode

The protocols for High-Speed (HS), Low-Speed (LS), and Fast-Speed (FS) Modes are identical except the bus speed for HS Mode is 3.4 MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a start condition. The master code is sent in Fast or Fast Plus Mode (maximum 1 MHz clock); slaves do not ACK this transmission.

The master then generates a repeated start condition that causes all slaves on the bus to switch to HS Mode. The master then sends I2C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a stop bit is sent by the master. While in HS Mode, packets are separated by repeated start conditions.



READ AND WRITE TRANSACTIONS

Table 22. BIT DEFINITIONS

Symbol	Definition								
S	START								
А	ACK. The slave drives SDA to 0 acknowledge the preceding packet.								
Ā	NACK. The slave sends a 1 to NACK the preceding packet.								
R	REPEATED START								
Р	STOP								
 7 bits S Slave Address 	Jave Address 0 0 8 0 8 0 8 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 7 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0 8 0								
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SOLUTION DESIGN RECOMMENDATION

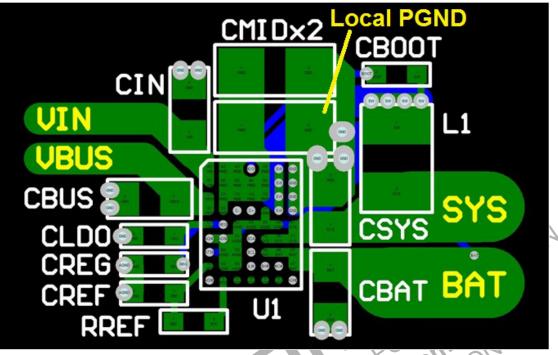


Figure 55. Recommended Component Placement and Routing

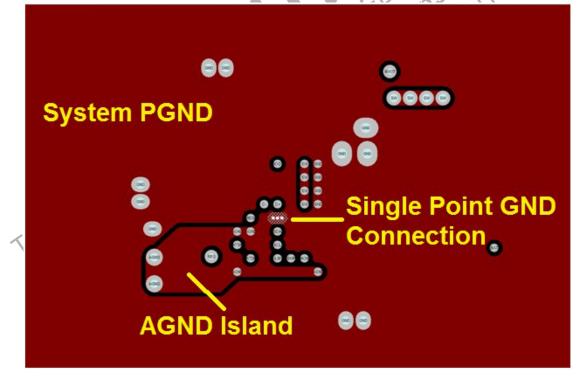


Figure 56. Recommended GND Connections

REGISTER AND BIT DESCRIPTIONS

The default states of the registers are with only the battery connected (VBUS and VIN not connected).

Table 23. I²C REGISTER MAP

REG NAME	ADR	DEFAULT	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STATUS 0	00h	1000_0010	RESERVED	VINPWR	VBUSPWR	PWROK	STAT	PRE	SLEEP	NOBAT
STATUS 1	01h	0000_0000	LOIBAT	CHG	DET	CHGCMP	TOCHG	DIVC	BOOST	BATLO
STATUS 2	02h	0000_0000	INPUTSEL	INPUTOVP	TEMPSD	TEMPFB	JEITA	TBAT	WDTTO	TMRTO
INT 0	04h	0000_0000	VALFAIL	VININT	VBUSINT	VLOWTH	CHGEND	CHGMOD	WKBAT	BATINT
INT 1	05h	0000_0000	IBATLO	RCHGN	BSTOVP	BSTTSD	BSTFAIL	BATUVL	BSTWDTTO	VBATLV
INT 2	06h	0000_0000	TOCMP	OVPINPUT	SHORTBAT	ICTEMP	BATTEMP	OTGOCP	BATOCP	TIMER
MINT 0	08h	0000_0000	MVALFAIL	MVININT	MVBUSINT	MVLOWTH	MCHGEND	MCHGMOD	MWKBAT	MBATINT
MINT 1	09h	0000_0000	MIBATLO	MRCHGN	MBSTOVP	MBSTTSD	MBSTFAIL	MBATUVL	RESERVED	MVBATLV
MINT 2	0Ah	0000_0000	MTOCMP	MOVPINPUT	MSHORTBAT	MICTEMP	MBATTEMP	MOTGOCP	MBATOCP	MTIMER
CONTROL 0	0Ch	0011_1111	RESE	RVED		VLOWV			VBATMIN	7
CONTROL 1	0Dh	0101_0111	GP02	GPO1	LDO_OFF	VL	DO	RESERVED	VS	YS
CONTROL 2	0Eh	0001_1100	CONT	RESERVED	RCHGDIS	NOBATOP	TE	TOEN	HZMODE	RESERVED
CONTROL 3	0Fh	0100_0000	RESET	TRE	GTH	RESE	RVED	PPOFFSLP	PPOFF	CE#
VFLOAT	11h	0110_1001				FLO	AT	En		
IOCHRG	12h	0001_0000	RESE	RVED			IOCH	IRG		
IBAT	13h	1001_1000		ITEF	RM			PRE	CHG	
IBUS	14h	0001_0000	RESERVED				IBUSLIM	e C		
VBUS	15h	0010_0100	RESE	RVED	VBU	SOVP	ans and	VBUS	SLIM	
IIN	16h	0001_1011	RESERVED			N		111		
VIN	17h	0001_0100	RESE	RVED	VIN	OVP	, VUL	VIN	LIM	
NTC	18h	0000_1111	RESE	RVED	TEMPDIS	NTCOK	NTC4	NTC3	NTC2	NTC1
TIMER	19h	0001_1011	TMRRST	WDEN	RESERVED	PRE	TMR		FCTMR	
SAFETY	1Ah	1111_1111		2F	- KM	SAFE	TY			
TOPOFF	1Bh	0000_0011		RESEF	IVED		TO_BDETDIS		TOTMR	
BOOST	1Ch	0001_0010	RESERVED OTG BOOSTEN RESERVED VBOOST							
DPLUS	1Fh	0000_0000	FORCEDET	SV 1	14	RESE	RVED			SETTMR0
MONITOR 0	20h	1000_0110	ITERMCMP	VBATCMP	VLOWVCMP	BATSHORT	HIVBAT	IBUS#	ICHG#	CV
MONITOR 1	21h	1010_0XXX	RESERVED	PMIDVBAT	PPON	BUCKON	ISRCCMP	NTCGND	DISPIN	ILIMPIN
IC_INFO	2Dh	10XX_XXXX	VENDO	R CODE		PN			REV	
FEATURE CONTROL	30h	0010_0000	WDTEXP	RESERVED	DIVCON	DISREF	RESE	RVED	RESE	RVED

Table 24. I²C REGISTER DESCRIPTIONS

STATUS 0				Register Address: 00h	Default Value = 1000 0010		
Bit	Name	Value	Туре	Descri	ption		
7	RESERVED	1	R	Reserved. This bit should always read "1".			
6	VINPWR	0	R	A "1" indicates that an input source voltage at V _{IN} has risen above V _{SOURCE(RISE)} and passed validation, and a valid VBUS is not present. To maintain a "1" V _{SOURCE(FALL)} < V _{IN} < V _{INOVP} and V _{IN} > V _{BAT} + V _{SLP} . VINPWR will not be set to "1" if VBUSPWR = "1".			
5	VBUSPWR	0	R	A "1" indicates that an input source voltage at V _{BUS} has risen above V _{SOURCE(RISE)} and passed validation. To maintain a "1" $V_{SOURCE(FALL)} < V_{BUS} < V_{BUSOVP}$ and $V_{BUS} > V_{BAT} + V_{SLP}$.			
4	PWROK	0	R	If HZ state is entered while PWROK is set to " PWROK will not reset to "0" until after the sour	A "1" indicates that $V_{BAT} > V_{LOWV}$ during charging. If HZ state is entered while PWROK is set to "1" and then V_{BAT} falls below V_{LOWV} , PWROK will not reset to "0" until after the source is re-validated and the IC returns to Charge Mode. Validation occurs whenever the part exits HZ State.		
3	STAT	0	R	A "1" indicates the /STAT pin is pulled low when charging is being performed. This bit goes to "0" during Top–Off charging.			
2	PRE	0	R	A "1" indicates that the charger is in Pre-Charge mode and a "0" indicates it is not. In con- junction with the STAT (REG 00h[3]) bit, the system processor can determine the type of charging being performed.			
1	SLEEP	1	R	A "1" indicates that the charger is in sleep mod available input source voltage drops below the V_{BAT} + V_{SLP} or v_{SOURCE} (FALL).	le. Sleep mode is entered when the highest higher of		
0	NOBAT	0	R	A "1" indicates that the IC has determined ther	e is no battery connected.		
	STATU	S 1		Register Address: 01h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descri	ption		
7	LOIBAT	0	R	A "1" indicates that the battery is present but the threshold when TE= "0" or TOEN = "1".	ne current has fallen below the I_{TERM}		
6:5	CHGDET		RN	Identifies the type of charger adapter connecters completed. (FAN54510A, FAN54512A only) Binary Adapter Type 00 Detection not completed 01 SDP 10 CDR 11 DCP	ed to the VBUS input after adapter detection		
4	CHGCMP	0	R	A ^{«1} " indicates that the battery is charged (I _{BAT} < ITERM) and that charging has completed when TE = "1". This bit remains "0" during Top-Off charging.			
3	TOCHG	0	R	A "1" indicates Top-Off charging mode.			
2	DIVC	0	R	A "1" indicates that the Dynamic Input Voltage Control loop is active. If DIVC = "1", the INPUTSEL (REG 02h[7]) status bit indicates whether the V_{BUSLIM} or V_{INLIM} voltage control loop is active.			
1	BOOST	0	R	A "1" indicates the device is in boost mode.			
0	BATLO	0	R	A "1" indicates that V_{BAT} < 3.0 V during Boost	Operation only.		

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	STATU	S 2		Register Address: 02h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descrip	otion		
7	INPUTSEL	0	R	Indicates which input is routed to PMID whene VIN. Binary Input 0 VBUS 1 VIN	ver a valid source is connected to VBUS or		
6	INPUTOVP	0	R	A "1" indicates that V _{BUS} and/or V _{IN} is higher than its OVP threshold. Switching is stopped to protect the IC and the BATFET (Q4) is turned on to support the system load. If INPUTOVP = "1", the INPUTSEL status bit (REG 02h[7]) state indicates whether the OVP condition exists on V _{BUS} or V _{IN} .			
5	TEMPSD	0	R	A "1" indicates the charger is in thermal shutdo	wn.		
4	TEMPFB	0	R	A "1" indicates the charger is in thermal regulat	tion.		
3	JEITA	0	R	A "1" indicates the battery temperature is outsiduring battery charging, charge current and flot has stopped, and NTC (REG 18h[3:0]) = "0000 See (REG 18h[5:0]) for details on NTC operational structure of the stopped struc	at voltage have been reduced or charging ","0001","0111", or "1111".		
2	TBAT	0	R	A "1" indicates the battery temperature is unsat stopped and NTC (REG 18h[3:0]) = "0000" or " See (REG 18h[5:0]) for details on NTC operation	ʻ1111"		
1	WDTTO	0	R	A "1" indicates the 100sec Watch Dog Timer ha watch dog timer expires, registers are reset to 19h[6]) control bit is cleared. Setting WDEN (REG 19h[6]) = "1" or a re-inse back to "0".	their default values and the WDEN (REG		
0	TMRTO	0	R	A "1" indicates the safety timer expired during I A re-insertion of VBUS or VIN will reset WDTT	Pre-Charge or Fast Charge. O back to "0".		
	INT 0			Register Address: 04h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descrip			
7	VALFAIL	0	RC	A "1" indicates that V_{BUS} or V_{IN} validation faile	d.		
6	VININT	0 NCE	RC	VIN Plug In: A "1" indicates V _{IN} > V _{SOURCE(RIS} ready present. VIN Plug Out: A "1" indicates V _{IN} < V _{SOURCE(F} VBUS Plug Out with VIN Present: A "1" indicat terrupt will not occur, though, until V _{BUS} < V _{SO}	ALL) or V _{IN} < V _{BAT} +V _{SLP} . es that V _{IN} > V _{SOUBCE} (BISE). This VIN in-		
5	VBUSINT	0	RC	VBUS Plug In: A "1" indicates V _{BUS} > V _{SOURC} VBUS Plug Out: A "1" indicates V _{BUS} < V _{SOUR}	E(RISE)· ICE(FALL) or V _{BUS} < V _{BAT} +V _{SLP} .		
4	VLOWTH	0	RC	A "1" indicates the battery voltage has risen above or fallen below the V_{LOWV} threshold during charging or $V_{BAT} > V_{LOWV}$ at the start of charging. The interrupt will also occur at Plug Out if $V_{BAT} > V_{LOWV}$.			
3	CHGEND	0	RC	A "1" indicates that the device has completed a normal charge cycle where I_{BAT} has fallen below the I_{TERM} threshold if TE = "1". If configured to do so, the IC may continue charging in Top Off with CHGEND = "1".			
2	CHGMOD	0	RC	A "1" indicates that the charging mode has cha Charge modes.	nged between Pre-Charge and Fast		
1	WKBAT	0	RC	A "1" indicates the battery is below the V_{BATMIN} at Plug In.	A "1" indicates the battery is below the V _{BATMIN} threshold set in VBATMIN (REG 0Ch[2:0])		
0	BATINT	0	RC	A "1" indicates that the IC has determined the I See NOBAT (REG 00h[0]) status bit.	battery presence has changed state.		

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	INT	1		Register Address: 05h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descr	iption		
7	IBATLO	0	RC	A "1" indicates that the charging current has risen above or fallen below I_{TERM} when TE = "0". The LOIBAT (REG 01h[7]) status bit should also be read to determine if the actu al charging current is above or below the I_{TERM} threshold.			
6	RCHGN	0	RC	A "1" indicates that the battery voltage has fallen by $V_{\mbox{RCHG}}$ below $V_{\mbox{FLOAT}}$ after charging has completed.			
5	BSTOVP	0	RC	A "1" indicates that VBUS has risen above the boost OVP threshold.			
4	BSTTSD	0	RC	A "1" indicates that the IC junction temperature threshold, T _{REGTH} , during boost operation.	re has exceeded the temperature shutdown		
3	BSTFAIL	0	RC	V_{BUS} fails to achieve the voltage required to a sustained (>50 $\mu s)$ current limit during the box			
2	BATUVL	0	RC	A "1" indicates that the battery voltage fell bel V_{BAT} < UVLO _{BST} when the boost is first enable	low UVLO _{BST} during boost operation or that led.		
1	BSTWDTTO	0	RC	A "1" indicates the 100sec Watch Dog Timer	has timed out during Boost Operation.		
0	VBATLV	0	RC	Provides an interrupt bit for indicating that the Operation. Boost operation will continue until	battery has fallen below 3.0 V during Boost either BOOSTEN = "0" or $V_{BAT} < UVLO_{BST}$.		
	INT :	2		Register Address: 06h Default Value = 0000 0000			
Bit	Name	Value	Туре	Description			
7	ТОСМР	0	RC	A "1" indicates that Top-Off charging has con timer when both TE="1" and TOEN="1".	npleted with the expiration of the Top-Off		
6	OVPINPUT	0	RC	A "1" indicates that the V _{BUS} or V _{IN} voltage has risen above or fallen below the OVP threshold. See INPUTOVP (REG 02h[6]) Status bit.			
5	SHORTBAT	0	RC	A "1" indicates that V_{BAT} has fallen below V_{SH}	HORT during charging.		
4	ICTEMP	0	RC	A "1" indicates that the IC temperature has risen high enough to trigger Thermal Regula- tion (T _{REGTH}), or Thermal Shutdown (T _{SHUTDOWN}). If ICTEMP = "1", see TEMPFB (REG 02h[4]) and TEMPSD (REG 02h[5]) Status bits to determine if the device is in Thermal Regulation or Thermal Shutdown.			
3	BATTEMP	0	RC	A "1" indicates that the battery temperature has If BATTEMP = "1", see NTC (REG 18h[5:0]) f	5		
2	OTGOCP	0	RC	A "1" indicates that the boost did not success	fully pass the Short Check State.		
1	BATOCP	10	RC	A "1" indicates that the BATFET (Q4) has exc	eeded its discharge current limit.		
0	TIMER	0	RC	If running from the Safety Timer, a "1" indicate Fast Charge has expired. See TMRTO (REG If running from the Watch Dog Timer, a "1" ind in boost or charge operation.	02h[0]) Status bit.		
	MINT	0		Register Address: 08h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descr	iption		
7	MVALFAIL	0	R/W	Writing a "1" masks VALFAIL = "1" from driving the /INT pin LOW.			
6	MVININT	0	R/W	Writing a "1" masks VININT = "1" from driving the /INT pin LOW.			
5	MVBUSINT	0	R/W	Writing a "1" masks VBUSINT = "1" from driving the /INT pin LOW.			
4	MVLOWTH	0	R/W	Writing a "1" masks LOWTH = "1" from driving the /INT pin LOW.			
3	MCHGEND	0	R/W	Writing a "1" masks CHGEND = "1" from drivi	ng the /INT pin LOW.		
2	MCHGMOD	0	R/W	Writing a "1" masks CHGMOD = "1" from driv	ing the /INT pin LOW.		
1	MWKBAT	0	R/W	Writing a "1" masks WKBAT = "1" from driving	g the /INT pin LOW.		
0	MBATINT	0	R/W	Writing a "1" masks BATINT = "1" from driving	g the /INT pin LOW.		

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	MINT	1		Register Address: 09h	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descr	iption		
7	MIBATLO	0	R/W	Writing a "1" masks IBATLO = "1" from driving	g the /INT pin LOW.		
6	MRCHGN	0	R/W	Writing a "1" masks RCHGN = "1" from driving	g the /INT pin LOW.		
5	MBSTOVP	0	R/W	Writing a "1" masks BSTOVP = "1" from drivir	ng the /INT pin LOW.		
4	MBSTTSD	0	R/W	Writing a "1" masks BSSTSD = "1" from drivin	ng the /INT pin LOW.		
3	MBSTFAIL	0	R/W	Writing a "1" masks BSTFAIL = "1" from drivin	ng the /INT pin LOW.		
2	MBATUVL	0	R/W	Writing a "1" masks BATULV = "1" from drivin	g the /INT pin LOW.		
1	Reserved	0	R				
0	MVBATLV	0	R/W	Writing a "1" masks VBATLV = "1" from driving	g the /INT pin LOW.		
	MINT	2		Register Address: 0Ah	Default Value = 0000 0000		
Bit	Name	Value	Туре	Descr	iption		
7	MTOCMP	0	R/W	Writing a "1" masks TOCMP = "1" from driving	g the /INT pin LOW.		
6	MOVPINPUT	0	R/W	Writing a "1" masks OVPINPUT = "1" from driving the /INT pin LOW.			
5	MSHORTBAT	0	R/W	Writing a "1" masks SHORTBAT = "1" from dr	iving the /INT pin LOW.		
4	MICTEMP	0	R/W	Writing a "1" masks ICTEMP = "1" from drivin	g the /INT pin LOW.		
3	MBATTEMP	0	R/W	Writing a "1" masks BATTEMP = "1" from driving the /INT pin LOW.			
2	MOTGOCP	0	R/W	Writing a "1" masks OTGOCP = "1" from driving the /INT pin LOW.			
1	MBATOCP	0	R/W	Writing a "1" masks BATOCP = "1" from driving the /INT pin LOW.			
0	MTIMER	0	R/W	expires and will, therefore, not mask /INT bit.			
D '4	CONTR			Register Address: 0Ch	Default Value = 0011 1111		
Bit 7:6	Name Reserved	Value 00	Type R	Descr	iption		
5:3			PLF	This sets the good battery voltage threshold of er is available to the user. Binary V _{LOWV} (V) 000 3.0 001 3.1 010 3.2 011 3.3 100 3.4 101 3.5 110 3.6 111 3.7	on the BAT pin, above which full system pow-		
2:0	VBATMIN	111	R/W	This sets the voltage threshold on the BAT pin VBATMIN should not be set lower than the m Binary V_{BATmin} (V) 000 2.7 001 2.8 010 2.9 011 3.0 100 3.1 101 3.2 110 3.3 111 3.4			

Table 24. I²C REGISTER DESCRIPTIONS (continued)

CONTROL 1				Register Address: 0Dh	Default Value = 0101 0111		
Bit	Name	Value	Туре	Description			
7	GPO2	0	R/W	A "1" enables GPO2 to output logic high. GPO2 is s FAN54511AP, FAN54513A only)	sourced by the LDO. (FAN54511A,		
6	GPO1	1	R/W	A "1" enables GPO1 to output logic high. GPO1 is sourced by the LDO. (FAN54511A, FAN54511AP, FAN54513A only)			
5	LDO_OFF	0	R/W	A "1" disables the LDO.			
4:3	VLDO	10	R/W	Sets the LDO output voltage. The LDO input is sou Binary V _{LDO} (V) 00 3.30 01 3.60 10 4.95 11 5.05	rced from PMID.		
2	Reserved	1	R		CN .		
1:0	VSYS	11	R/W	Regulated system voltage in Pre-Charge Mode (V) grammed 250mV, or more, above the minimum regavailable input power, V_{SYS} can be up to 250 mV b Binary V_{SYS} (V) 00 3.3 01 3.4 10 3.5 11 3.6	uired system voltage. With limited		
	CONTR	OL2		Register Address: 0Eh	Default Value = 0001 1100		
Bit	Name	Value	Туре	Description	Mr.		
7	CONT	0	w	Writing a "1" ignores a Pre-Charge or Fast Charge lows the IC to continue charging. However, the TM TIMER (REG 06h[0]) interrupt bit will still be set to A "0" will reset all registers except SAFETY and pu the Pre-Charge or Fast Charge Safety Timer expir CONT does not affect the watchdog timer or top-of "0".	RTO (REG 02h[0]) status bit and '1" upon timer expiration. t the charger IC into IDLE State when es.		
6	Reserved	0	R	CE CAT			
5	RCHGDIS	, e E	R/W	Writing a "1" disables the automatic recharge functing a fails below $V_{FLOAT}-V_{RCHG}.$	ion with TE = "1" when the battery volt-		
4	поватор	1	R/W	For a "0", if no battery is detected during source plu charge) is reached, the charger will not perform an buck converter will stay on and the BATFET turns of tinue to run with no battery. For a "1" if no battery is detected during source plu charge) is reached, the charger will perform a batter battery is connected. The buck converter will stay of ing the host processor to continue to run with no bat	additional battery absence test. The off allowing the host processor to con- g-in or when a Full Battery (end of ery absence test every 2 seconds until a on and the BATFET (Q4) turns off allow-		
3	TE	1	R/W	A "1" enables charge current termination and a "0" < I _{TERM} .	allows charging to continue even if I_{BAT}		
	TOEN	1	R/W	A "1" enables the Top–Off charging.			
2			1	A "1" puts the IC in the High-Z state. This bit will be	internal where BOOOTEN "d" but		
2	HZMODE	0	R/W	device will return to HZ state when BOOSTEN is so The bit will reset to "0" when V_{BAT} falls below V_{BAT} this bit are ignored.	et back to "0".		

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	CONTR	OL3		Register Address: 0Fh	Default Value = 0100 0000
Bit	Name	Value	Туре	Descri	iption
7	RESET	0	R/W	Writing a "1" resets all registers to their defaul Read returns "0".	lts: writing a "0" has no effect.
6:5	TREGTH	10	R/W	Temperature threshold at which the current is overheating.BinaryTREGTH (°C)007001851010011120	reduced to prevent the device from
4:3	Reserved	0	R		
2	PPOFFSLP	0	R/W	PPOFFSLP is for automatic Ship Mode entry removed. When PPOFFSLP is set to a "1", PI when V_{BUS} or V_{IN} falls below $V_{SOURCE(FALL)}$. PPOFFSLP will be reset to "0" once a valid in	POFF will be automatically written to "1"
1	PPOFF	0	R/W	Writing a "1" to this bit turns the BATFET (Q4) supplemental mode is not allowed. <u>Bit Reset Behavior</u> PPOFFSLP = "1" (Ship Mode): PPOFF and P input source is connected. PPOFFSLP="0": PPOFF will be reset to "0" w connected.	POFFSLP will be reset to "0" when a valid hen a valid input source is either removed or
0	CE#	0	R/W	During a normal charging condition, a "0" ena BATFET (Q4) but will allow the battery to sup V _{BAT} .	bles the BATFET, Q4 and a "1" disables the plement the SYS load when V _{SYS} falls below
	THISDE	EVICE	S N PLE REPE	During a normal charging condition, a "0" ena BATFET (Q4) but will allow the battery to sup V _{BAT} .	

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	VFLO	AT		Register A	ddress: 11h	Default Value=0110 1001
Bit	Name	Value	Туре		D	escription
7:0	FLOAT	01101001	Type R/W	Charger output "float" Programmable from 3 Hex VFLOAT(V) 00 3.30 01 3.31 02 3.32 03 3.33 04 3.34 05 3.35 06 3.36 07 3.37 08 3.38 09 3.39 0A 3.40 0B 3.41 0C 3.42 0D 3.43 0E 3.44 0F 3.45 10 3.46 11 3.47 12 3.48 13 3.49 14 3.50 15 3.51 16 3.52 17 3.53 18 3.54 19 3.55 1A 3.56 1B 3.57 1C 3.58 1D 3.59 1E 3.61 <	voltage, VFI OAT.	0 mV increments. Default is 4.35 V

Table 24. I²C REGISTER DESCRIPTIONS (continued)

IOCHRG				Register Address: 12h	Default Value=0001 0000
Bit	Name	Value	Туре	Descr	iption
7:6	Reserved	00	R		
				Sets the typical battery charging current, I _{OCI} Programmable from 0.200 A to 3.200 A in 50	_{HRG} , during Fast Charging. mA increments. Default is 1.000 A.
5:0	IOCHRG	010000	R/W	Hex I _{OCHRG} (A) Hex I _{OCHRG} (A) 00 0.200 15 1.250 01 0.250 16 1.300 02 0.300 17 1.350 03 0.350 18 1.400 04 0.400 19 1.450 05 0.450 1A 1.500 06 0.500 1B 1.550 07 0.550 1C 1.600 08 0.600 1D 1.650 09 0.650 1E 1.700 0A 0.700 1F 1.750 0B 0.750 20 1.800 0C 0.800 21 1.850 0D 0.850 22 1.900 0E 0.900 23 1.950 0F 0.950 24 2.000 10 1.050 26 2.100 12 1.100 27 2.150 13	Hex I _{OCHRG} (A) 2A 2.300 2B 2.350 2C 2.400 2D 2.450 2E 2.500 2F 2.550 30 2.600 31 2.650 32 2.700 33 2.750 34 2.800 35 2.850 36 2.900 37 2.950 38 3.000 39 3.050 3A 3.100 3B 3.150 3C 3.200
				Bits 3Dh - 3	
	IBA	Г	1	Register Address: 13h	Default Value = 1001 1000
Bit	Name	Value	Туре		iption
7:4	ITERM	1001	R/W S PLE	Sets the termination current threshold, J_{TERM} Programmable from 100 mA to 600 mA. DefaIf TE = "1" and the charge current falls belowwill stop.Binary I_{TERM} (A)0000Reserved0001Reserved0010Reserved00110.10001000.12501010.15001100.17501110.200	ult is 300 mA.
	-HISV	- <	2EP	Sets the typical battery charging current, I _{PP} , Programmable from 200 mA to 800 mA. Defa	ult is 450 mA.
3:0	PRECHG	1000	R/W	Binary I _{PP} (A) 0000 Reserved 0011 Reserved 0010 Reserved 0011 0.200 0100 0.250 0101 0.300 0110 0.350 0111 0.400	BinaryIpp (A) 1000 0.450 1001 0.500 1010 0.550 1011 0.600 1100 0.650 1101 0.700 1110 0.750 1111 0.800

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	IBU	S		Register Address: 1	14h	Default Value	e = 0001 0000
Bit	Name	Value	Туре		Descri	iption	
7	Reserved	0	R				
6:0	IBUSLIM	0010000	R/W ISI	This sets the maximum input of Programmable from 100 mA to There are 3 FET segmentation 23h (975 mA), and 24h (1000 table for the associated $R_{DS(0)}$ Hex Isustim (A) 00 0.100 01 0.125 02 0.150 150 1F 03 0.175 04 0.200 05 0.225 06 0.250 07 0.275 08 0.300 25 09 09 0.325 00 0.400 29 0D 00 0.425 00 0.425 02 0.450 03 0.375 03 0.375 04 0.350 05 0.475 06 0.475 07 0.475 08 0.375 09 0.325 01 0.500 02 02 03 0475 04 0.600 11 0.525 12 0.650 <	o 3.00 A in 25 m n ranges: 00h (1 mA) to 7Fh (30	A steps. Default is 500 100 mA) to 08h (300 m. 00 mA). Refer to the El Hex I _{BUSLIM} (A) 3A 1.550 3B 1.575 3C 1.600 3D 1.625 3E 1.650 3F 1.675 40 1.700 41 1.725 42 1.750 43 1.775 44 1.800 45 1.825 46 1.850 47 1.850 47 1.875 48 1.900 49 1.925 48 1.900 49 1.925 48 1.975 40 2.000 40 2.025 48 2.050 44 2.050 44 2.050 51 2.125 52 2.150 53 2.175 54 2.200 55 2.225 56 2.250) mA. A). 09h (325 mA) to

Table 24. I²C REGISTER DESCRIPTIONS (continued)

This table defines the operation of each register bit for all IC versions. Default values are with VBAT = 3.8 V and VBUS = VIN = open.

	VBU	s		Register Address: 15h	Default Value = 0010 0100
Bit	Name	Value Type Description			cription
7:6	Reserved	00	R		
5:4	VBUSOVP	10	R/W	$\begin{array}{llllllllllllllllllllllllllllllllllll$	
3:0	VBUSLIM	0100	R/W	regulate to in a charging scenario where a 6 VBUS. Binary V _{BUSLIM} (V) 0000 4.240 0001 4.320 0010 4.400 0011 4.480 0100 4.560 0101 4.640 0110 4.720 0111 4.800	the Dynamic Input Voltage Control loop will current-limited weak adapter is connected to

the provide the pr

Table 24. I²C REGISTER DESCRIPTIONS (continued)

This table defines the operation of each register bit for all IC versions. Default values are with VBAT = 3.8 V and VBUS = VIN = open.

IIN Bit Name Value Type				Register Address: 16h	Default Value = 0001 1011
Bit	Name	Value	Туре	Desc	ription
7	Reserved	0	R		
				This sets the maximum input current limit fro Programmable from 325 mA to 2 A in 25 mA	
6:0	IINLIM	0011011	R/W	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Hex INLIM (A) 3A 1.775 3B 1.800 3C 1.825 3D 1.850 3E 1.875 3F 1.900 40 1.925 41 1.950 42 1.975 43 2.000 AB A A A A A A A A A A A A A A A A A A
				Bits 44h - 7	Fh = 2.000 A
	THIS D	EVICE	ISN PLE REPE	1A 0.975 37 1.700 1B 1.000 38 1.725 1C 1.025 39 1.725 39 1.750 Bits 44h - 7	

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Table 24. I²C REGISTER DESCRIPTIONS (continued)

	VIN			Register Address: 17h	Default Value = 0001 0100
Bit	Name	Value	Туре	Descri	ption
7:6	Reserved	00	R		
5:4	VINOVP	01	R/W	$\begin{array}{c c} \mbox{This sets the V_{IN_OVP}$ threshold.} \\ \hline \mbox{Binary} & V_{IN_OVP}$ (V) \\ 00 & 6.5 \\ 01 & 10.5 \\ 10 & 13.7 \\ 11 & \mbox{Reserved} \end{array}$	
3:0	VINLIM	0100	R/W		-limited weak adapter is connected to VIN.
	NTC	;		Register Address: 18h	Default Value = 0000 1111
Bit	Name	Value	Туре	Descri	ption
7:6	Reserved	00	R	FUCAUORI	
5	TEMPDIS	0	R/W	This controls whether the NTC circuit affects t surements will continue to be updated every 1 Binary NTC Operation NTC measurement affects charge p NTC measurement does not affect	second in the NTC1 – 4 monitor bits.
4	NTCOK	10	R	"0" if NTC is either shorted to ground, open or	shorted to REF.
3	NTC4	1	R	A "1" indicates that NTC is above the T4 thres	shold. (Note 14)
2	NTC3	1	R	A "1" indicates that NTC is above the T3 thres	shold. (Note 14)
1	NTC2	1	R	A "1" indicates that NTC is above the T2 thres	shold. (Note 14)
0	NTC1	1	R	A "1" indicates that NTC is above the T1 thres	shold. (Note 14)

Table 24. I²C REGISTER DESCRIPTIONS (continued)

TIMER				Register Address: 19h	Default Value = 0001 1011
Bit	Name	Value	Туре	Descri	ption
7	TMRRST	0	W	Writing a "1" resets the Watch Dog Timer; writ Reading this bit always returns "0".	ing a "0" has no effect.
6	WDEN	0	R/W	Writing a "1" enables the Watchdog timer (t_{WD}) and disables the Safety timer.
5	Reserved	0	R		
				These bits set the Pre-Charge safety timer. SETTMR0 (REG 1Fh[0] must be set to "1" imr is changed to restart the timer in the program	
4:3	PRETMR	11	R/W	BinaryPre-Charge Safety Timer00Follows FCTMR (REG 19h[2:0]) pro01100 seconds1015 minutes1136 minutes	ogramming
				This sets the Fast Charge safety timer.	GIGIN
2:0	FCTMR	011	R/W	Binary Fast Charge Safety Timer (Hours) 000 Never Expires 001 4 010 6 011 8 100 10 101 12 110 14 111 16	OR NEW DEST
	SAFE	ТҮ		Register Address: 1Ah	Default Value = 1111 1111
Bit	Name	Value	Туре	Descri	
				These bits set the maximum programmable F	LOAT (REG 11h[7:0]) value.
7:4	VSAFE		RW	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	
				These bits set the maximum programmable IC	DCHRG (REG 12h[5:0]) value.
3:0	ISAFE	1111	R/W	Binary I _{OCHRG} Max. (Hex) I _{OCHRG} Max 0000 00 0.20 0001 04 0.40 0010 08 0.60 0011 0C 0.80 0100 10 1.00 0101 14 1.20 0110 18 1.40 0111 1C 1.60 1000 20 1.80 1001 24 2.00 1010 28 2.20 1011 2C 2.40 1100 30 2.60 1111 34 2.80 1111 3C 3.20	x. (A)

Table 24. I²C REGISTER DESCRIPTIONS (continued)

	торо	FF		Register Address: 1Bh	Default Value = 0000 0011
Bit	Name	Value	Туре	Desc	ription
7:4	Reserved	0000	R		
3	TO_BDETDIS	0	R/W	Setting this bit "1" disables the periodic batte	ry check during top-off charging.
2:0 Bit	TOTMR BOOS	011 ST Value	R/W	This sets the Top-Off charge timer. Binary Top Off Timer (min.) 000 Never Expires 001 10 010 20 011 30 100 40 101 50 110 60 111 70	Default Value = 0001-0010.
			Туре	Desc	ripuon
7 6	Reserved OTG	0	R R/W	Connects PMID to VBUS when the boost is This will reset when BOOSTEN = "0".	enabled (BOOSTEN = "1").
5	BOOSTEN	0	R/W	BOOSTEN Switch-Mode 0 Charge 1 Boost	N bit and the OTG bit will reset.
4	Reserved	1	R		
3:0	VBOOST	C 0010	IS N PLF R/WF	$\begin{array}{c c} \mbox{This sets the boost converter output voltage,} \\ \mbox{Programmable from 4.947 V to 5.347 V in 26} \\ \mbox{Binary V}_{BOOST}(V) \\ \mbox{0000 4.947} \\ \mbox{0001 4.973} \\ \mbox{0010 5.000} \\ \mbox{0011 5.027} \\ \mbox{0101 5.027} \\ \mbox{0101 5.080} \\ \mbox{0101 5.107} \\ \mbox{0111 5.133} \\ \mbox{1000 5.160} \\ \mbox{1010 5.160} \\ \mbox{1010 5.213} \\ \mbox{1010 5.240} \\ \mbox{1100 5.267} \\ \mbox{1101 5.293} \\ \mbox{1110 5.320} \\ \mbox{1111 5.347} \\ \end{array}$, V _{BOOST} . 5.67 mV steps. Default is 5.00 V.
	DPLU	IS	I	Register Address: 1Fh	Default Value = 0000 0000
Bit	Name	Value	Туре	Desc	ription
7	FORCEDET	0	R/W	Setting this bit to "1" forces a BC1.2 detectio	n on D+ and D–.
6:1	Reserved	000000	R	-	
0	SETTMR0	0	w	While operating on the Safety Timer a "1" res SETTMR0 must be set to "1" immediately aff 19h [4:3]) value is changed in order to restar Reading this bit always returns "0".	ter the Pre-Charge timer (PRETMR (REG

Table 24. I²C REGISTER DESCRIPTIONS (continued)

This table defines the operation of each register bit for all IC versions. Default values are with VBAT = 3.8 V and VBUS = VIN = open.

	MONITO	DR 0		Register Address: 20h	Default Value = 1000 0110	
Bit	Name	Value	Туре	Description		
7	ITERMCMP	1	R	I _{TERM} comparator output: "1" when I _{BAT} > ITERM reference or VBUS/ VIN not present.		
6	VBATCMP	0	R	Output of VBAT comparator: "1" when V _{BAT} > V _{BATMIN.}		
5	VLOWVCMP	0	R	Output of VLOWV comparator. In Fast Charge mode, a "1" indicates when $V_{BAT} > V_{LOWV}$. In Pre–Charge mode, a "1" indicates when $V_{SYS} > V_{BATMIN}$. In Boost mode, a "1" indicates when $V_{BAT} > VBATLV$ threshold.		
4	BATSHORT	0	R	A "1" indicates that $V_{BAT} > V_{SHORT}$ in any chacates that $V_{SYS} > UVLO_{BST}$.	arge mode or HZ. In Boost mode, a "1" indi-	
3	HIVBAT	0	R	A "1" indicates that V _{BAT} ≥ V _{FLOAT} when char	ge termination, TE bit is set to "0".	
2	IBUS#	1	R	A "0" indicates the I_{BUS} or I_{IN} loop is controlling	ng the battery charge current.	
1	ICHG#	1	R	A "0" indicates the I _{OCHRG} loop is controlling t	the battery charge current.	
0	CV	0	R	A "1" indicates the constant-voltage (CV) loop loops have released.	o is controlling the charger and all current	
	MONITO	DR 1		Register Address: 21h	Default Value = 1010 0XXX	
Bit	Name	Value	Туре	Descri	iption V	
7	Reserved	1	R		or ai N	
6	PMIDVBAT	0	R	A "1" indicates that V _{PMID} > V _{BAT} .	Gel TO	
5	PPON	1	R	A "1" if charging and $V_{BAT} > V_{SHORT}$ or if the	IC is in Standby or HZ.	
4	BUCKON	0	R	A "1" indicates the buck converter is on.	Rhi	
3	ISRCCMP	0	R	A "1" indicates that either V_{BUS} or V_{IN} has risen above $V_{SOURCE(RISE)}$ and is currently above $V_{SOURCE(RISE)}$. A "0" indicates that both V_{BUS} and V_{IN} are below $V_{SOURCE(FALL)}$.		
2	NTCGND	X	R	A "1" indicates that the NTC pin was tied to gr	ound at V _{BUS} POR.	
1	DISPIN	X	R	A "1" indicates that the DIS pin has been exte	rnally driven HIGH.	
0	ILIMPIN	x	R	A "1" indicates that the ILIM pin has been exte	ernally driven HIGH.	
	IC_INI	F0	10	Register Address: 2Dh	Default Value = 10XX XXXX	
Bit	Name	Value	Туре	Descri	iption	
7:6	Vendor Code	10	R	Identifies ON Semiconductor as the IC supplie	er.	
5:3	PN	XXX	R	Part numbers bits, see the Ordering Info in Ta	ble 2.	
2:0	REV	XXX	R	IC Revision		
	FEATURE C	ONTROL		Register Address: 30h	Default Value = 0010 0000	
Bit	Name	Value	Туре	Descri	iption	
7	WDTEXP	0	R/W	A "1" will reset all registers except SAFETY and put the charger IC into IDLE State when the Watch Dog Timer (WDT) expires.		
6	Reserved	0	R			
5	DIVCON	1	R/W	A "0" disables Dynamic Input Voltage Control (DIVC).		
4	DISREF	0	R/W	A "1" will disable the REF output and NTC fun	ctionality. JEITA not enforced.	
3	Reserved	0	R			
2	Reserved	0	R			
1	Reserved	0	R			
0	Reserved	0	R			

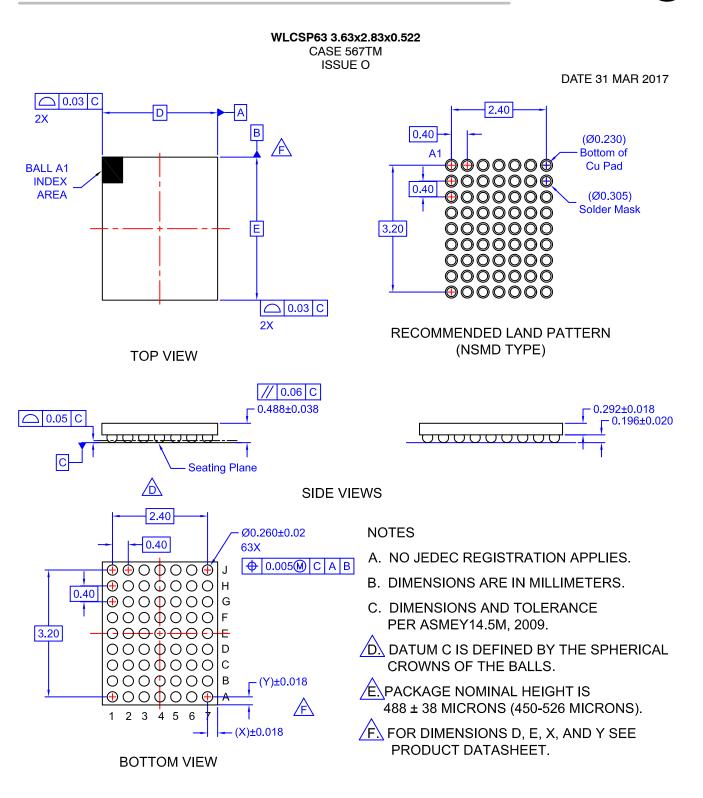
14. Without power from VBUS or VIN, the reference will not be powered and the NTC pin will be at ground. See applications section for more detail.

PRODUCT-SPECIFIC DIMENSIONS (MM)

Product	E	D	Х	Y
FAN5451xAUCX	3.63 ± 0.03	2.83 ±0.03	0.195	0.195







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